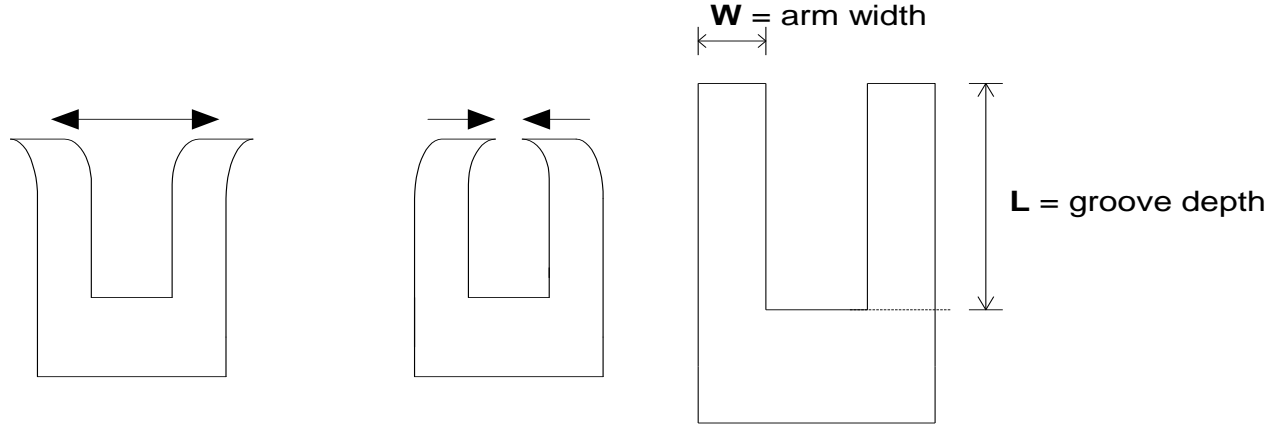
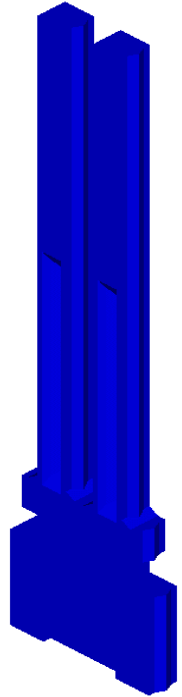


kHz Oscillator & RTC Workshop



Tuning Fork Crystal



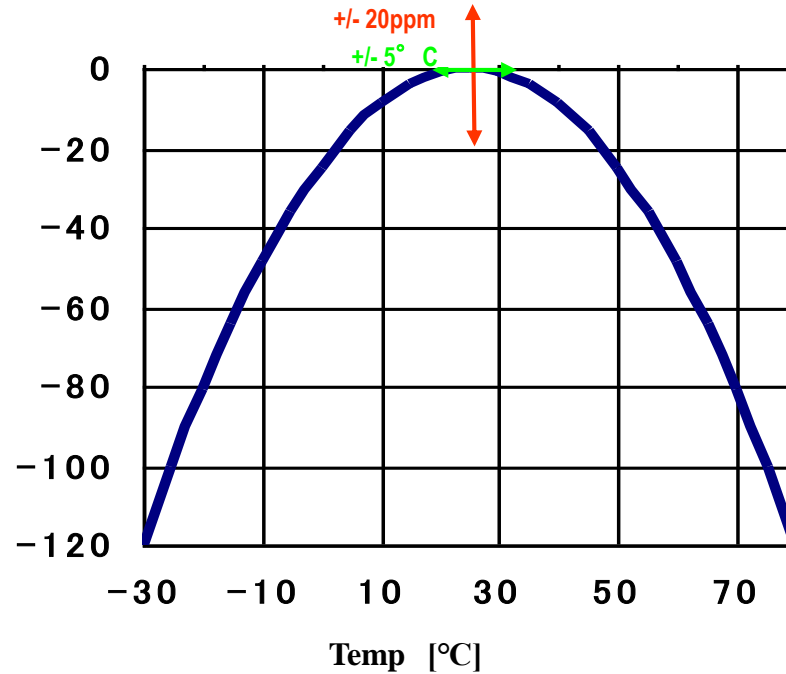
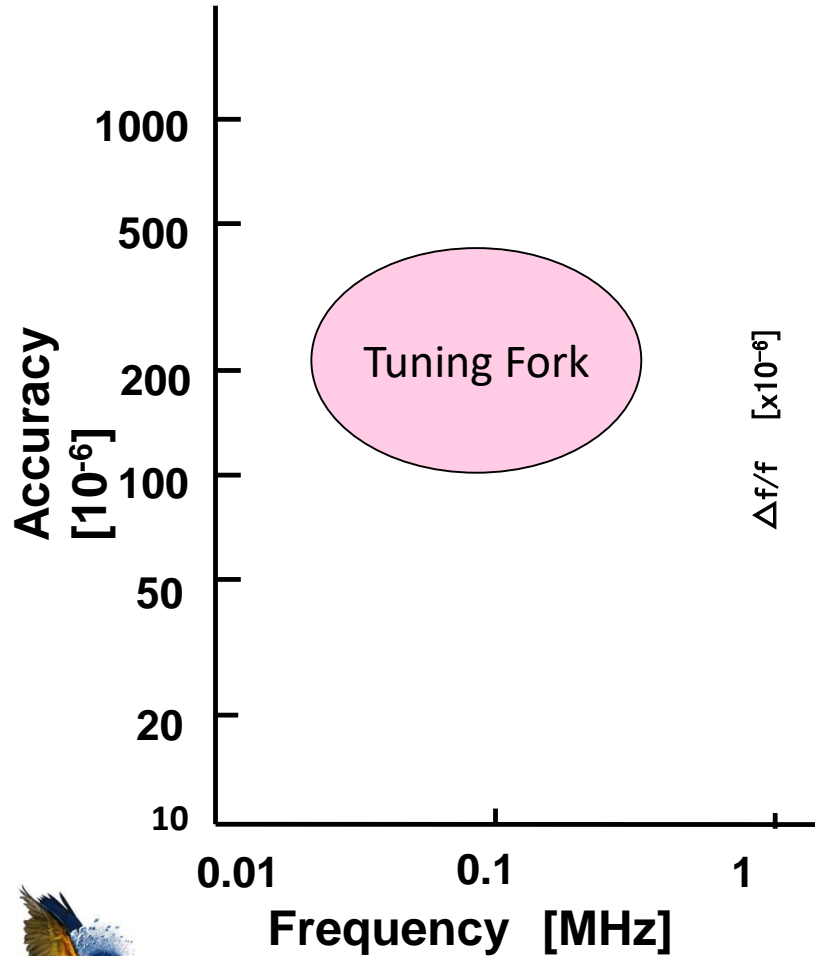
Flexure vibration
kHz frequencies

$$f = k \cdot \frac{W}{L^2}$$

k = constant



Tuning Fork Crystal



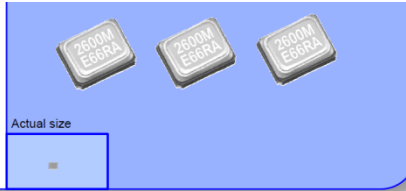
Frequency tolerance
 ± 20 to $\pm 100 \text{ ppm}$



TD Tolerance Specification

FA -128

- Nominal frequency range : 16 MHz to 54 MHz
- External dimensions : 2.0 × 1.6 × 0.5 mm
- Overtone order : Fundamental
- Applications : Mobile phone, Bluetooth, W-LAN
ISM band radio, Clock for MPU



Specifications (characteristics)

Item	Symbol	Specifications		Conditions / Remarks
		For RF Reference	For Clock	
Nominal frequency range	f_nom	16.000 MHz to 54.000 MHz		Fundamental Please contact us about available frequencies.
Storage temperature range	T_stg	-40 °C to +125 °C		Storage as single product.
Operating temperature range	T_use	-40 °C to +85 °C (+105 °C)		Please contact us about +85 °C < T_use
Level of drive	DL	100 µW Max.	200 µW Max.	Recommended: 1 to 100 µW
Frequency tolerance (standard)	f_tol	±10 × 10 ⁻⁶ ±1	±30 × 10 ⁻⁶	+25 °C, Please contact us for requirements not listed in this specifications.
Frequency versus temperature characteristics (standard)	f_tem	±10 × 10 ⁻⁶ ±1	±30 × 10 ⁻⁶	-20 °C to +75 °C, Please contact us for requirements not listed in this specifications.



Initial & FTC separate

Initial only!

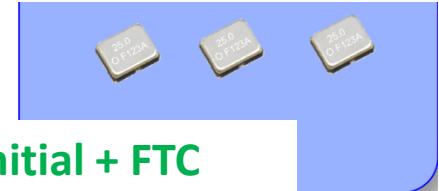
FTC via parabolic coefficients!

$$\Delta f/f = B(T_i - \theta X)^2$$

θX : specified temperature

SG-210 STF

- Frequency range : 1 MHz to 75 MHz
- Supply voltage : 1.6 V to 3.6 V
- Function : Standby (ST)
- External dimensions : 2.5 × 2.0 × 0.8 mm
- Operation temperature : -40 to +105 °C



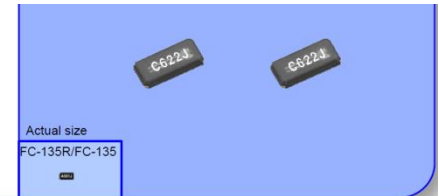
Initial + FTC

Specifications (characteristics)

Item	Symbol	Specifications		Conditions / Remarks
		1MHz to 75MHz	1.6V to 3.6V	
Output frequency range	f_o	1MHz to 75MHz		Please contact us about available frequencies.
Supply voltage	Vcc	1.8 V Typ. 1.6 V to 2.2 V	2.5 V Typ. 2.2 V to 3.6 V	
Storage temperature	T_stg	-40 °C to +125 °C		Storage as single product.
Operating temperature	T_use	-40 °C to +85 °C / -40 °C to +105 °C		
Frequency tolerance	f_tol	S: ±25 × 10 ⁻⁶ L: ±50 × 10 ⁻⁶ Y: ±50 × 10 ⁻⁶ , W: ±100 × 10 ⁻⁶		-20 °C to +70 °C -40 °C to +85 °C -40 °C to +105 °C

FC -135R / FC -135

- Frequency range : 32.768 kHz (32 kHz to 100 kHz)
- External dimensions : 3.2 × 1.5 × 0.80 mm ...FC-135R/FC-135
- Overtone order : Fundamental
- Applications : Small communications devices



Specifications (characteristics)

Item	Symbol	Specifications		Conditions / Remarks
		FC-135R	FC-135	
Nominal frequency range	f_nom	32.768 kHz	32.768 kHz 32 kHz to 77.5 kHz	Please contact us about available frequencies.
Storage temperature	T_stg	-55 °C to +125 °C		Storage as single product.
Operating temperature	T_use	-40 °C to +85 °C (+105 °C)		Please contact us about +85 °C < T_use
Level of drive	DL	0.5 µW (1.0 µW Max.)		Please contact us if you require 1.0 µW Max.
Frequency tolerance (standard)	f_tol	±20 × 10 ⁻⁶		+25 °C, DL=0.1 µW Please ask for tighter tolerance
Turnover temperature	Ti	+25 °C ±5 °C		
Parabolic coefficient	B	-0.04 × 10 ⁻⁶ / °C ² Max.		



Equivalent Circuit

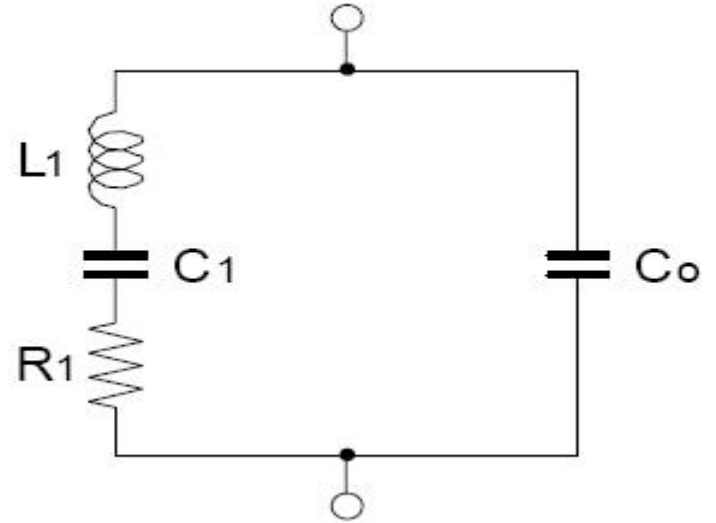
The Equivalent Circuit

L_1 – Dynamic or Motional Inductance (mH)

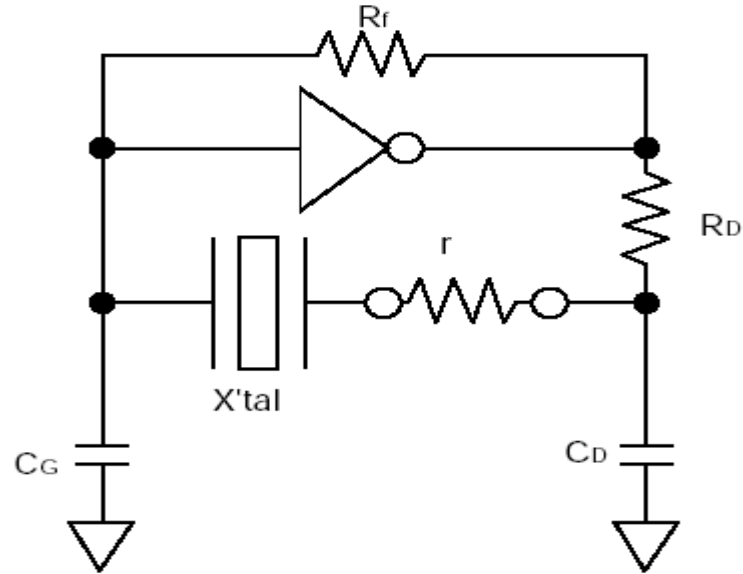
C_1 – Dynamic or Motional Capacitance (fF)

R_1 – Equivalent Series Resistance (ohms)

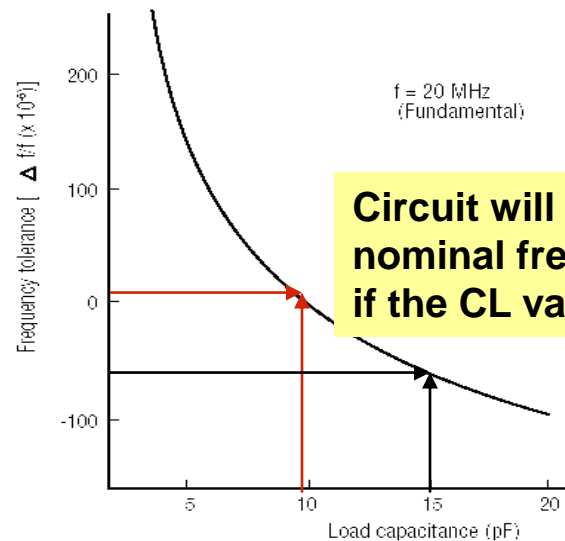
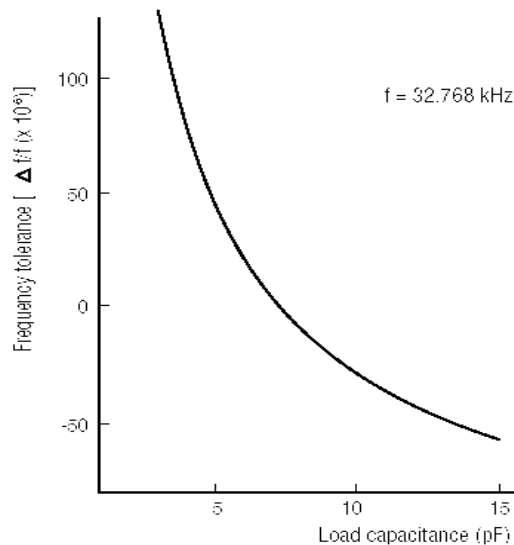
C_o – Parallel or Static Capacitance (pF)



Basic Oscillation Circuit



Calculation of Load Capacitance



Circuit will not oscillate at its nominal frequency if the CL value is not suitable.

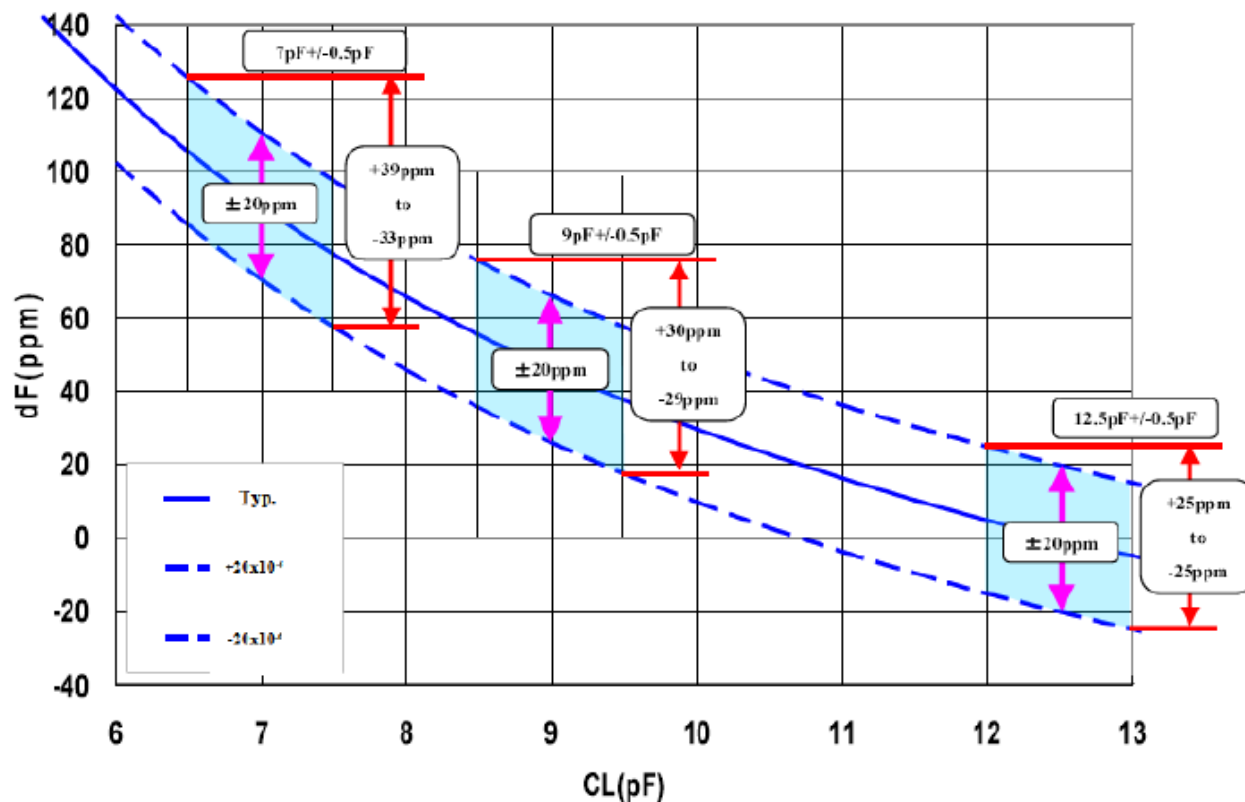
As shown in a left chart, the load capacity of the circuit changes when the value of C_G and C_D is changed, and the oscillation frequency of the oscillator is adjusted

The load capacity can calculate using the following formula.

$$CL \cong \frac{CG \times CD}{CG + CD} + CS \text{ (Stray capacity)}$$



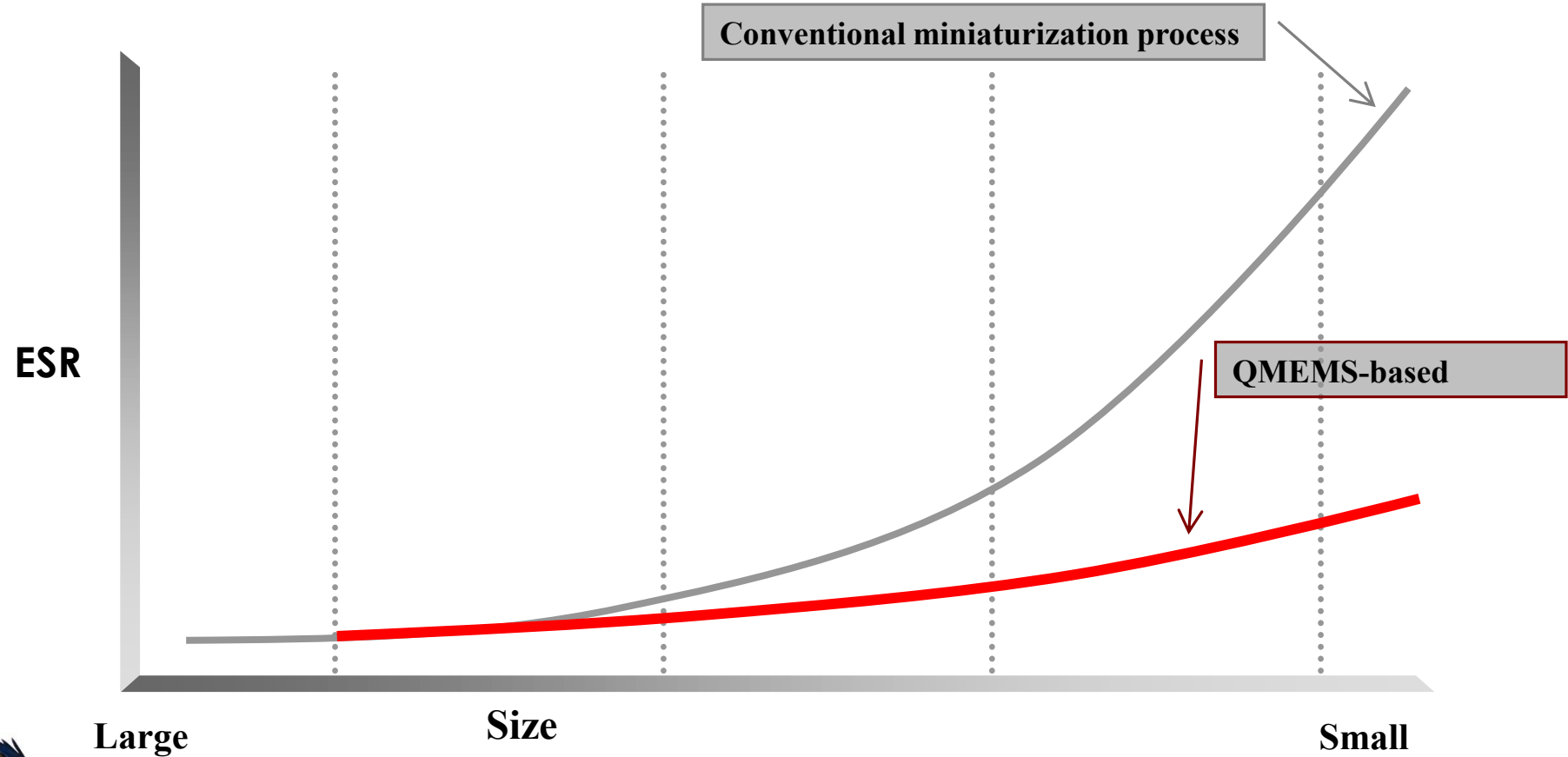
Calculation of Load Capacitance



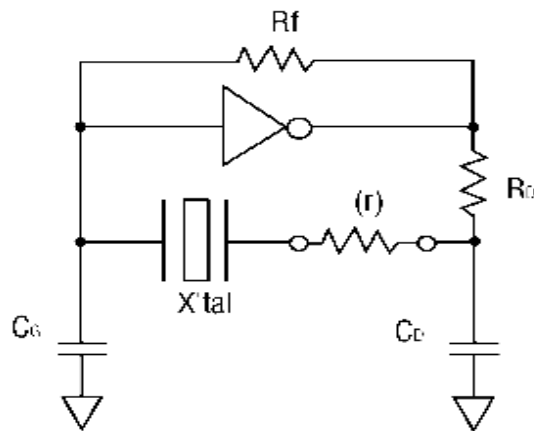
$$CL \cong \frac{CG \times CD}{CG + CD} + CS \text{ (Stray capacity)}$$



kHz XTAL ESR vs. Size



Oscillation Start-up Allowance



Oscillation circuit with negative resistance

Unless adequate negative resistance is allocated in the oscillation circuit, oscillation start-up time may be increase, or **NO OSCILLATION** may occur. In order to avoid this, provide enough negative resistance in the circuitry design.

How to check the allowance for oscillation

- (1) Connect the resistance (r) to the circuit in series with the crystal unit.
- (2) Adjust (r) so that oscillation can start (or stop).
- (3) Measure (r) when oscillation just starts (or stops) in (2) above.
- (4) Recommended $(r) > ESR \times (5 \text{ to } 10)$



XTAL Drive Level

Influence of drive level

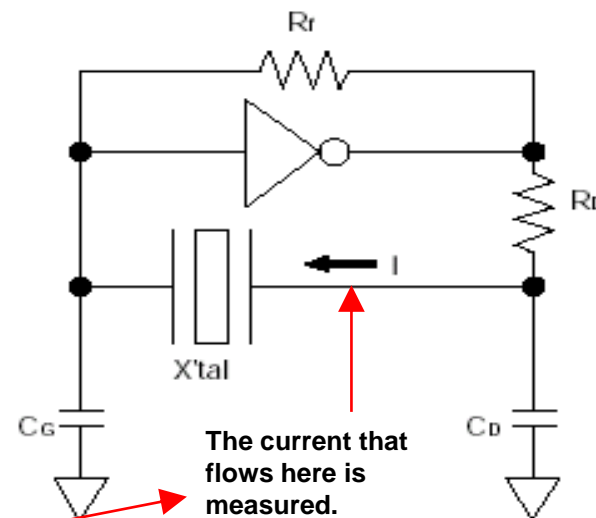
When the drive level is too large.

- The characteristic is deteriorated.
- Crystal could be destroyed.

When the drive level is too small.

- There is no oscillation.
- Becomes unstable even if oscillating.

$$\text{Drive level (P)} = I^2 R_e$$



$$R_e = R_1 \left(1 + \frac{C_0}{C_L} \right)^2 [\Omega]$$

XTAL Circuit parameters



RTC

Competition

RTC IC + Crystal



+



=

Epson

Integrated
Module



**Customer's
request**



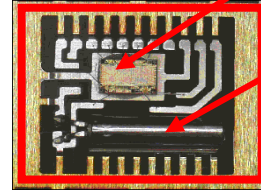
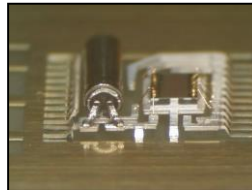
X'tal

**Tuning
folk**

RTC
Clock
Calendar
Alarm
Timer

Interfaces
I²C-BUS
3-Wire
4-Wire
4bit parallel

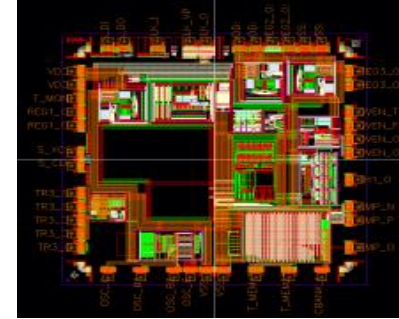
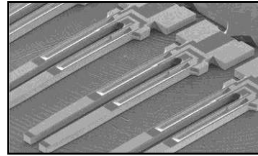
Other function
Built-in Memory
Voltage detect
Temp. sensor
Event-Detection
Power-switching
Battery charge control



RTC-IC

X'tal





Good combination – EPSON's unique point!!



Epson is the most Vertically Integrated

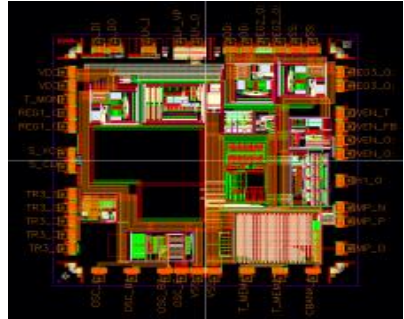
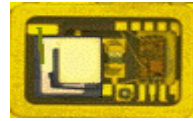
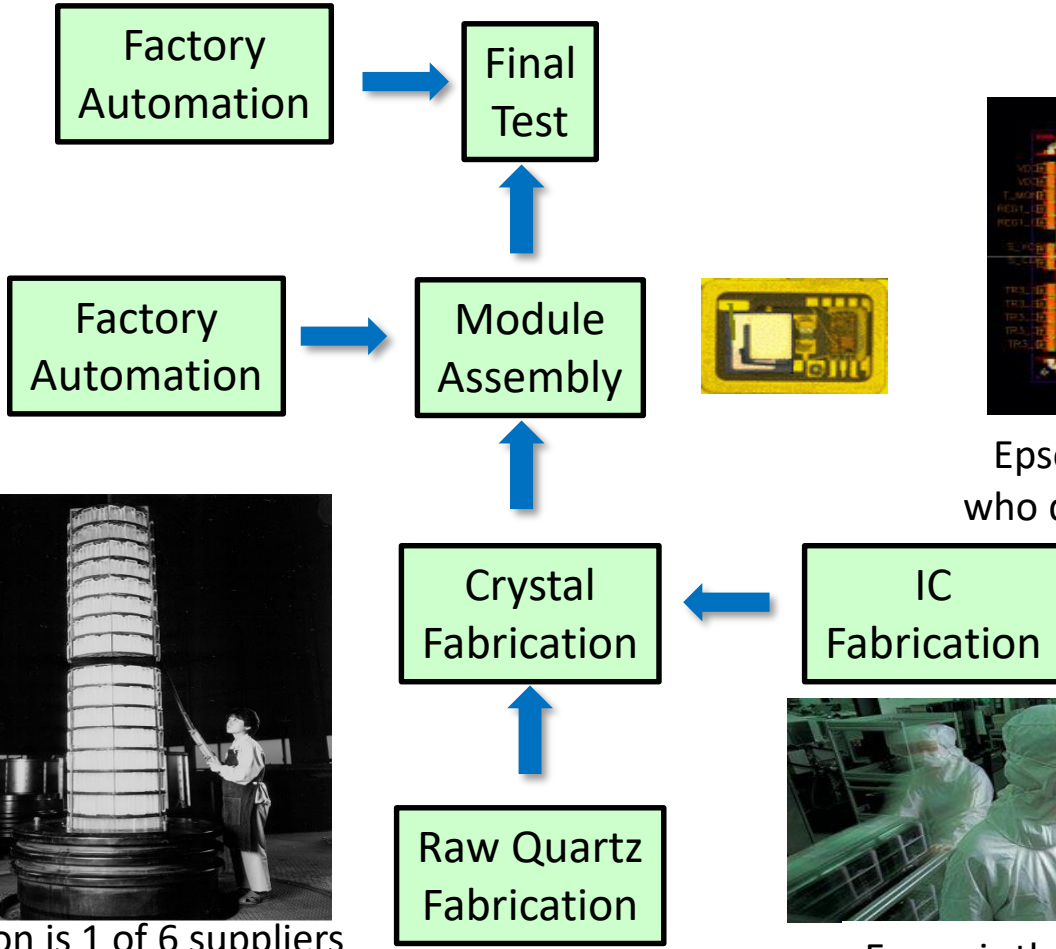


Epson is the only supplier who makes their own robots



Epson is 1 of 6 suppliers who grow their own Quartz

Epson Europe Electronics GmbH



Epson is 1 of very few who design their own ICs

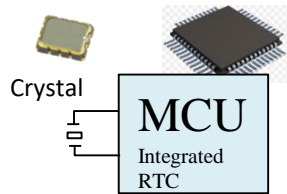


Epson is the only supplier with our own IC foundry



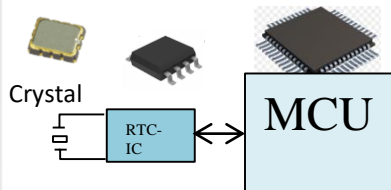
Options to realize RTC-Functions

TRADITIONAL OPTIONS



The MCU processor features an integrated RTC software function

- Low cost, but runs the risk of higher power consumption, low stability, calibration issues and oscillator circuit design issues.



The crystal is connected to the RTC externally

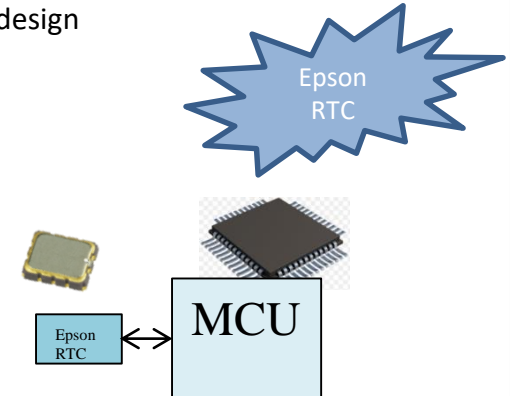
- Low power consumption, but requires circuit matching for stable oscillation

VS

TOTAL INTEGRATION

The crystal is integrated within the RTC module

- Low power consumption
- Extradentary accuracy
- High reliability
- Simple design



In most cases, the RTC is connected to MCU.



RTC Module Advantages

Which feature is the most important?



Easy Use / Tiny size / High reliability



Ultra low power consumption



Battery switching function with
optional battery charge control



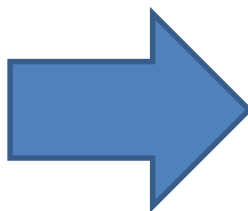
High accuracy for over temperature



Tiny Size



SA package
10.1x7.4x3.3mm



CE package
3.2x2.5x1.0mm



RX8900CE



RX8130CE





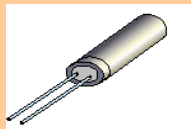
Since crystal matching has already been performed by us, there is no need for circuit evaluation to check the design and therefore customer can shorten development period.

Normal Guaranteed Frequency Accuracy

$5 \pm 23 \times 10^{-6}$ (at 25°C) \Rightarrow Equivalent to 1min/month

「RTC IC + 32k Xtal」 cannot easily achieve the above accuracy.

Xtal Tolerance
 $\pm 20\text{ppm}$ (Max)



+

IC Tolerance
 $\pm 10\text{ppm}$ (Max)



=

Total Tolerance
 $\pm 30\text{ppm}$ (Best Case)



Item	Symbol	Min.	Typ.	Max.	Unit
Oscillation start voltage	V _{STA}	1.1	—	5.5	V
Oscillation start time	t _{STA}	—	—	1	s
IC-to-IC frequency deviation ^{*1}	ΔIC	−10	—	+10	ppm

RTC IC Maker
Tolerance $\pm 10\text{ppm}$



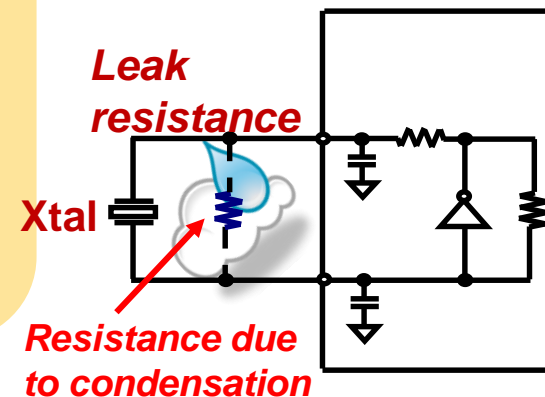
High Reliability

<RTCs operation environment>

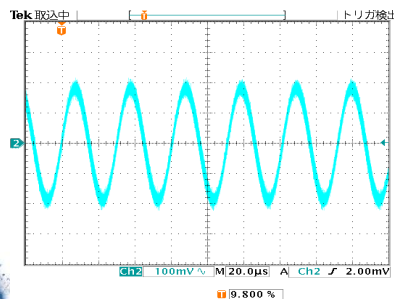
- ✓ RTC needs to run with very low voltage and current (power) and therefore **the circuit around Xtal is sensitive to the external environment (moisture,...)**.
- ✓ In case of `RTC IC + 32k Xtal` or `MCU(ASIC) + 32k Xtal`, the individual components are placed onto the PCB and thus influenced by external environment.



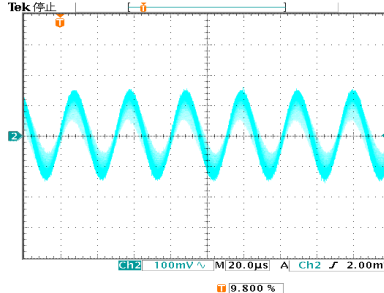
i.e. condensation can cause failures such as unstable oscillation (2) or no oscillation (3).



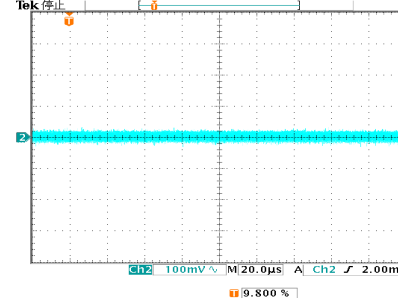
(1) Normal Oscillation



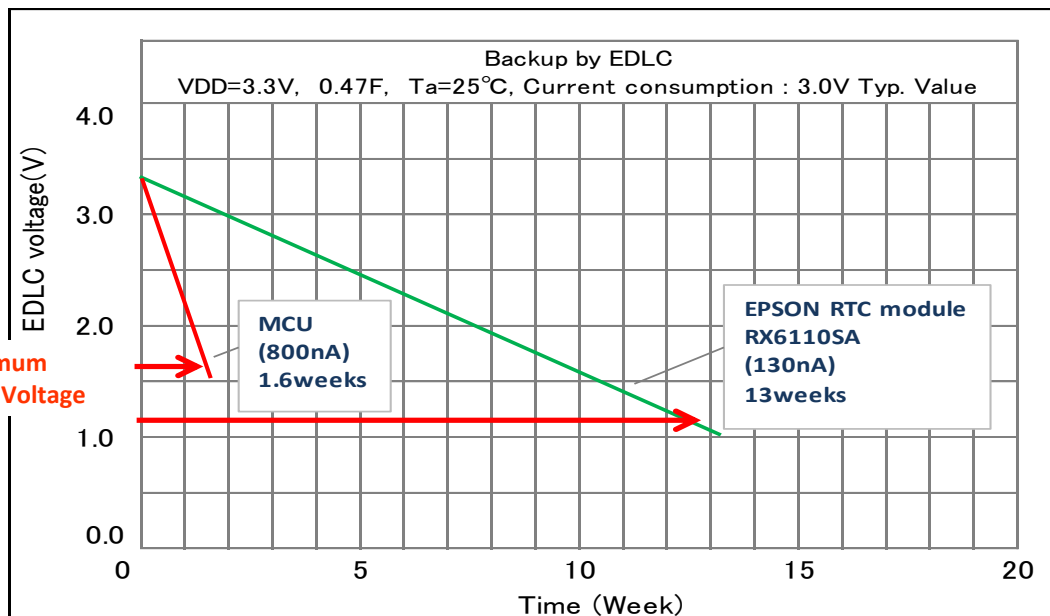
(2) Unstable Oscillation due to condensation.



(3) No Oscillation due to condensation



Low Power



RX6110SA
(Typ.130nA)



RX8010SJ
(Typ.160nA)

RTC Backup time simulation (Example)

※Back up by dual layer capacitor (Simulation)
(At 0.47F Typ value, not incl. self discharge.)

$$C = \frac{(I_{leakage} + I_{load}) [A] \times t [s]}{(V_0 - V_1) [V]}$$



Backup Switching Function

	RX6110SA	RX8900SA/CE RX8111/4111CE	RX8130CE	RX-8035SA/LC RX-4035SA/LC
Primary Supply	Powerline – constant supply voltage (on/off)	Powerline – constant supply voltage (on/off)	Any! As well discharging batteries	Any! As well discharging batteries
Backup Supply	EDLC or capacitors.	EDLC or capacitors.	Any! As well Lithium batteries!	Non rechargeable battery or EDLC.
Backup Battery Charge Control	Trickle charge for EDLC or capacitors	Trickle charge for EDLC or capacitors	Sophisticated user programmable charge control suitable as well for Lithium batteries!	Trickle charge for EDLC if short circuit between VOUT and VBAT

Other Power configurations are possible!
Please read white paper or contact us!!



RX6110SA



RX8900CE
RX8111CE



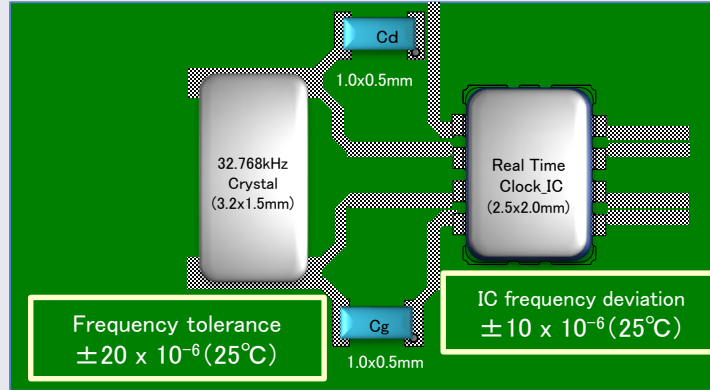
RX8130CE
(Safe function
for Lithium secondary
battery)



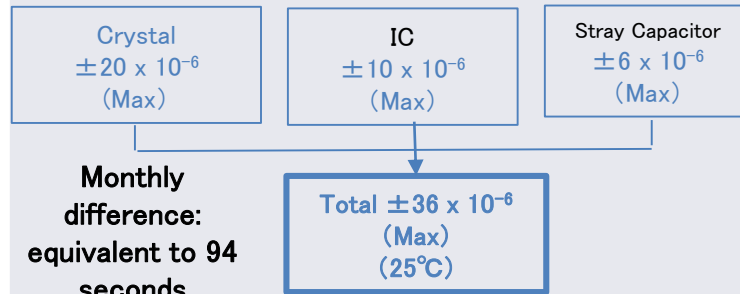
RX-8035SA/LC
RX-4035SA/LC



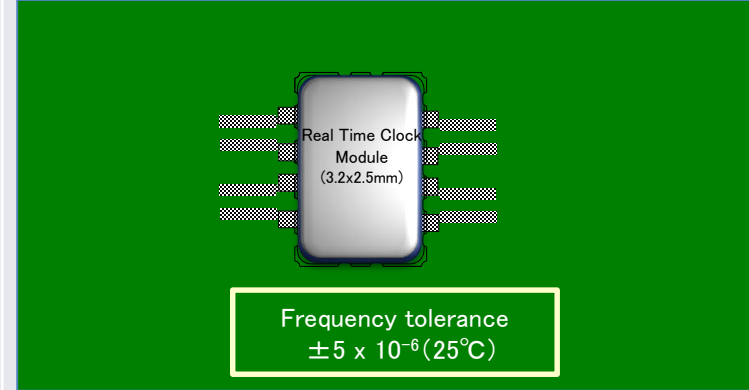
Crystal + IC



- There are many sources of variation in frequency (clock) accuracy



Real Time Clock Module



- Frequency (clock) accuracy has been adjusted
- Parts selection / evaluation, circuit evaluation (matching) also unnecessary

AA precision product
 $\pm 5 \times 10^{-6}$ (Max) (25°C)

Monthly difference:
equivalent to
13 sec

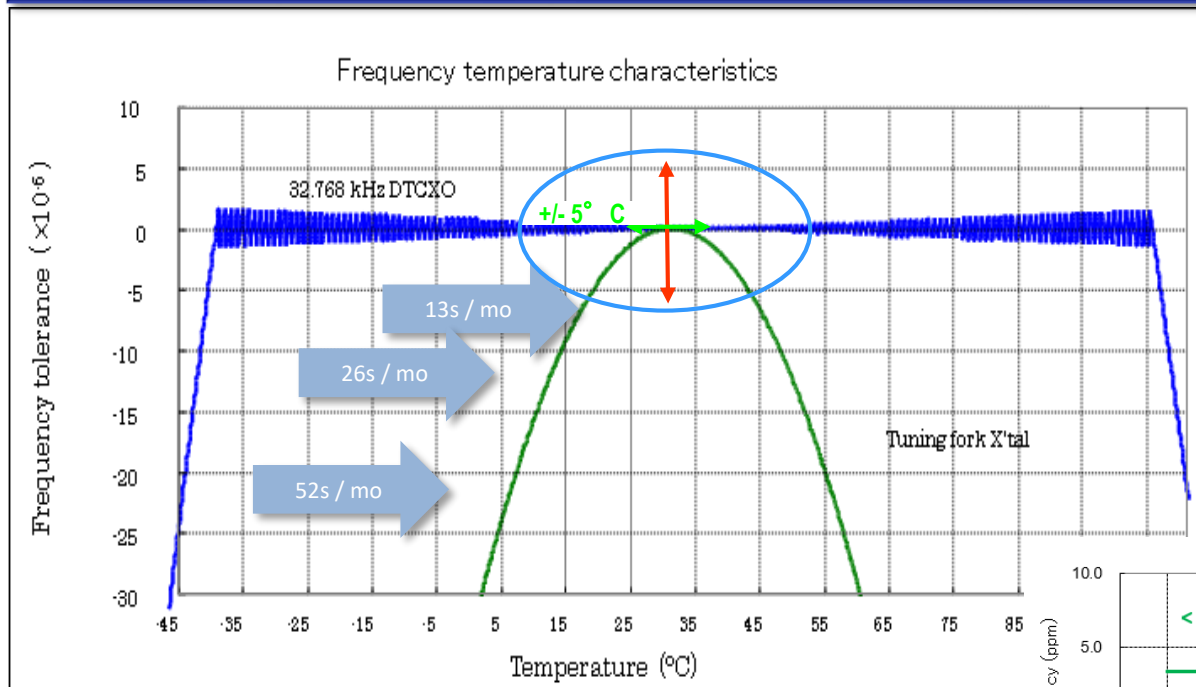
B precision product
 $\pm 23 \times 10^{-6}$ (Max) (25°C)

Monthly difference:
equivalent to
60 sec



High Stability over Temperature Range

Typical Frequency vs. Temp Characteristic

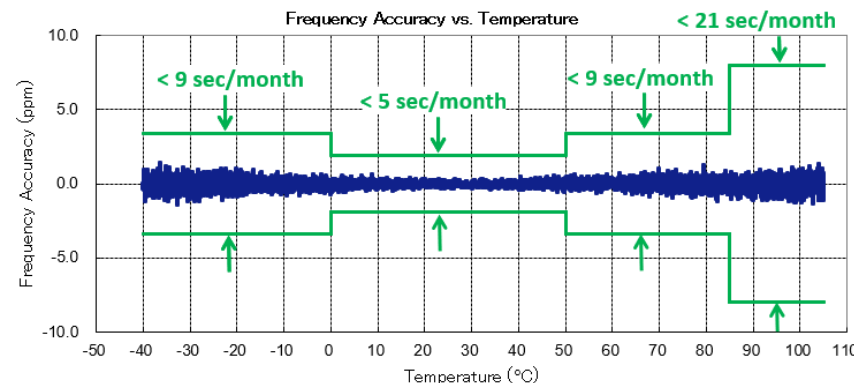


RX/A8900
RX/A8804

Built-in Compensation: multi-point FTC measurement and D-TCXO

$\pm 1.9\text{ppm}$ over -0 to $+50^{\circ}\text{C}$	=	< 5 sec/mth
$\pm 3.4\text{ppm}$ over -40 to $+85^{\circ}\text{C}$	=	< 9 sec/mth
$\pm 5.0\text{ppm}$ over -40 to $+85^{\circ}\text{C}$	=	< 13 sec/mth
$\pm 8.0\text{ppm}$ over $+85$ to $+105^{\circ}\text{C}$	=	< 21sec/mth

(RX8804CE)



RTC

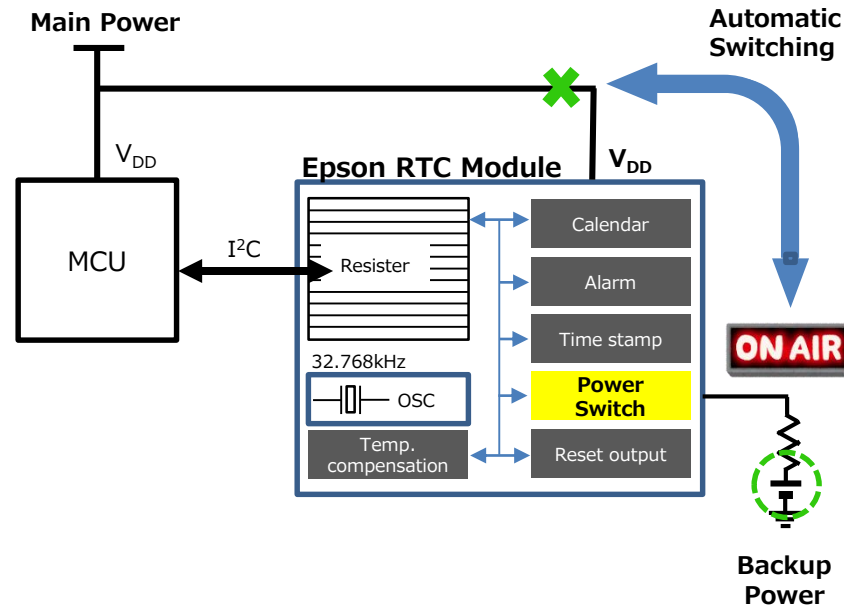
Additional Feature Options



Power Switch



This function monitors the main power condition, and will automatically change the power source to a backup supply when the voltage on the main power drops.



Advantages vs Diode-OR circuit

- Reduce leak current by using MOS switch inside RTC module.
- User doesn't need to care about VF/IR specification of Diode.

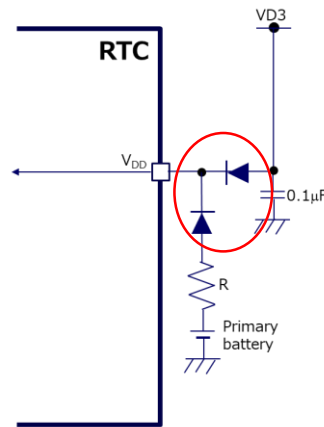
*Depends on backup battery type



Power Switch

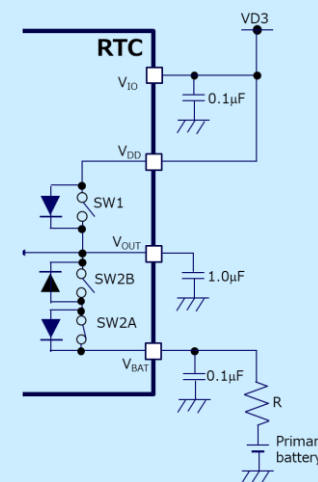
- Return to main power when the power returns
- Built in diode to prevent leakage current
- Recharging backup battery with low power consumption

External



- Schottky diode is recommended because of low voltage drop
- Schottky diode is expensive!
- Shorter battery life because of external diode

Internal



- No external diode
- Min leakage current
- Longer battery life

RX8111
RX4111
RX8130
RX8900
RX6110



Power Switch - Variants

	RX6110SA	RX8900SA/CE RX4111CE	RX8130CE	RX8111CE RX-8035SA/LC RX-4035SA/LC
Primary Supply	Powerline – constant supply voltage (on/off)	Powerline – constant supply voltage (on/off)	Any! As well discharging batteries	Any! As well discharging batteries
Backup Supply	EDLC or capacitors.	EDLC or capacitors.	Any! As well Lithium batteries!	Non rechargeable battery or EDLC.
Backup Battery Charge Control	Trickle charge for EDLC or capacitors	Trickle charge for EDLC or capacitors	Sophisticated user programmable charge control suitable as well for Lithium batteries!	Trickle charge for EDLC if short circuit between VOUT and VBAT

Other Power configurations are possible!



RX6110SA



RX8900CE
RX8111CE



RX8130CE
(Safe function
for Lithium secondary
battery)

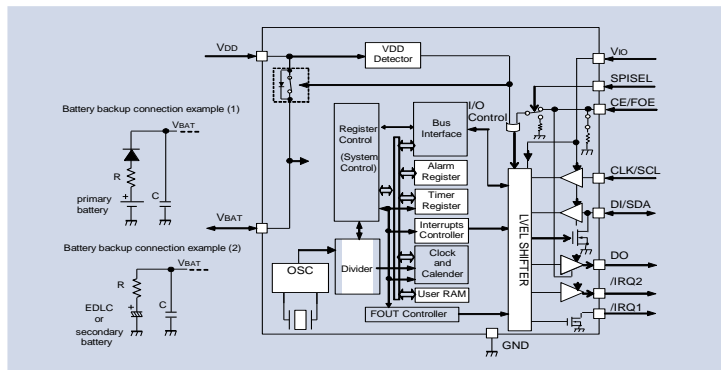


RX-8035SA/LC
RX-4035SA/LC

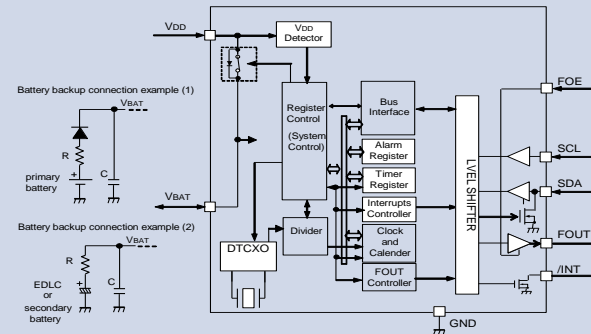


RTC with Power Switch – Backup Supply Connection Examples

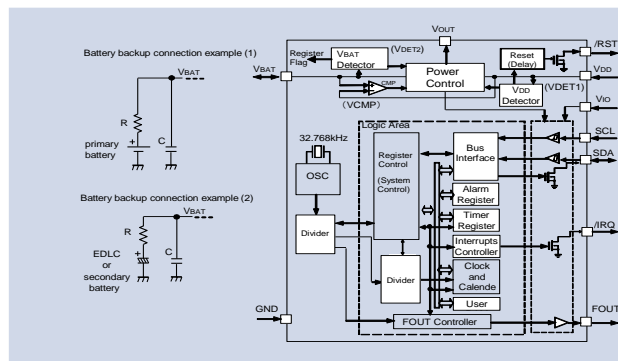
RX6110SA



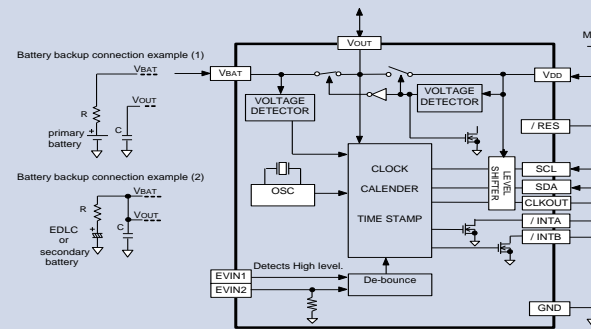
RX8900SA/CE



RX8130CE



RX-8035SA/LC, RX-4035SA/LC



Battery backup switchover function comparison

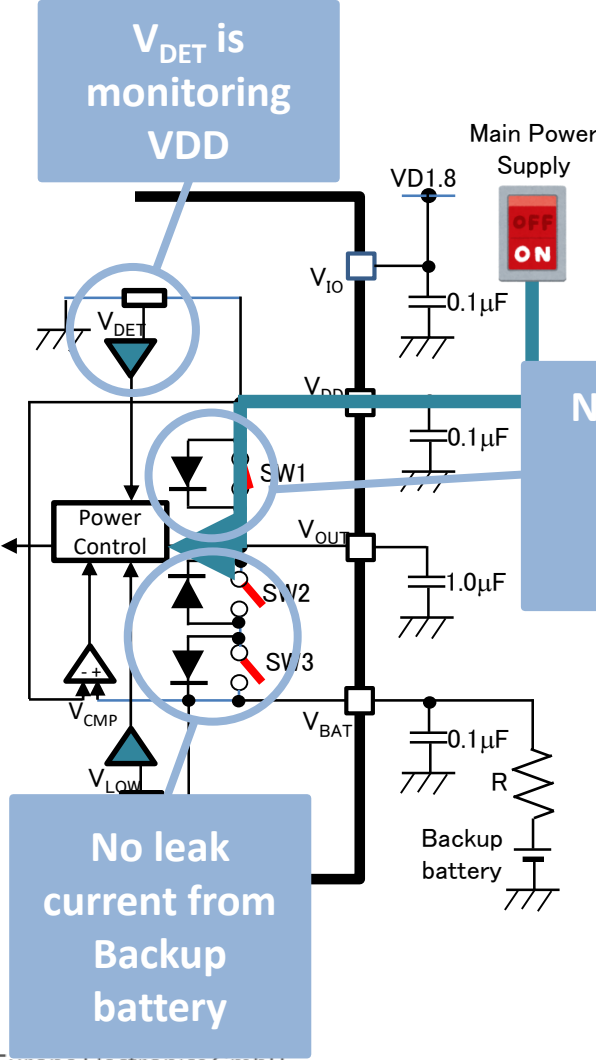
We have various types of circuits to realize the battery backup switchover function depending on the product

Detection voltage		RX8130CE	RX8111CE	RX4111CE	RX8900CE
Battery backup switchover function		Yes	Yes	Yes	Yes
Detection of V_{DD} voltage rise	Switch power supply from V_{BAT} to V_{DD}	Yes	Yes	Yes	Yes
Detection of V_{DD} voltage drop down	Switch power supply from V_{DD} to V_{BAT}	Yes When operation by main power supply Any time detection	Yes When operation by main power supply Any time detection	Yes When operation by main power supply Any time detection	Yes When operation by main power supply it is detected, every second
Detector threshold voltage rising edge of V_{BAT}	Charge stop voltage	Yes (3 level)	No	No	No
Detector threshold voltage falling edge of V_{BAT}	Recharge voltage	Yes (3 level)	No	No	No
Comparison of V_{BAT} and V_{DD}	When $V_{DD} \leq V_{BAT}$ Charge stop	Yes	Yes	No	No
Detection voltage of V_{BAT} low	Low V_{BAT} detection	Yes	Yes	No	No
Diode	V_{DD} side	Built-in	Built-in	Built-in	Built-in
	V_{BAT} side	Built-in	Built-in	External	External

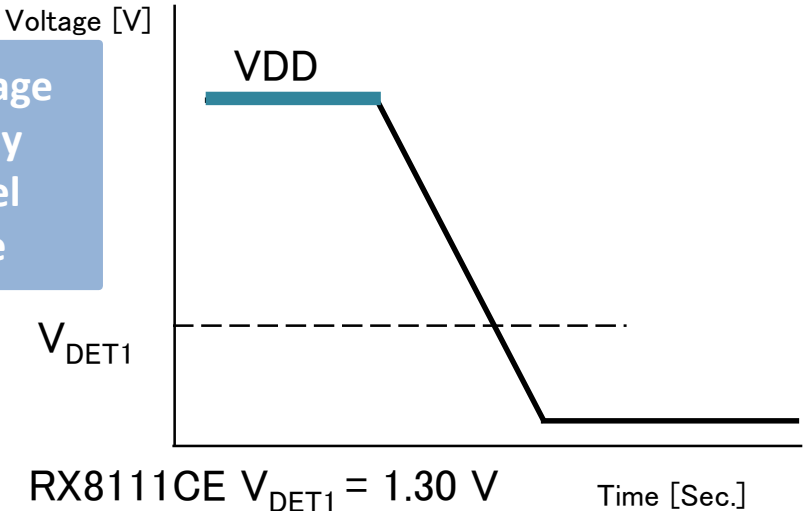
Designed to minimize leakage current and wasteful charging



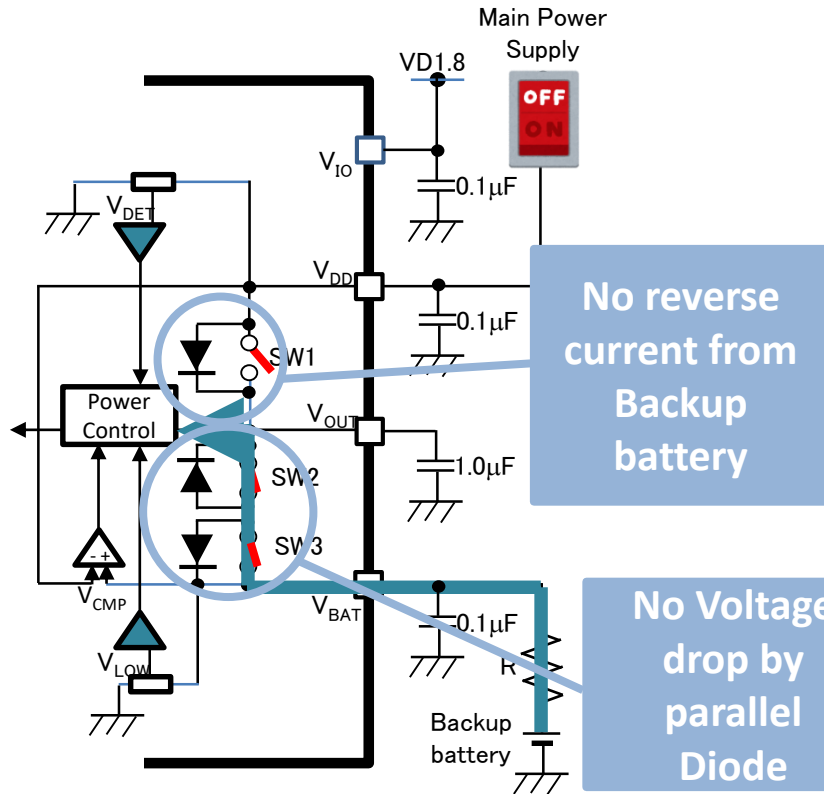
RX8111CE battery backup switchover



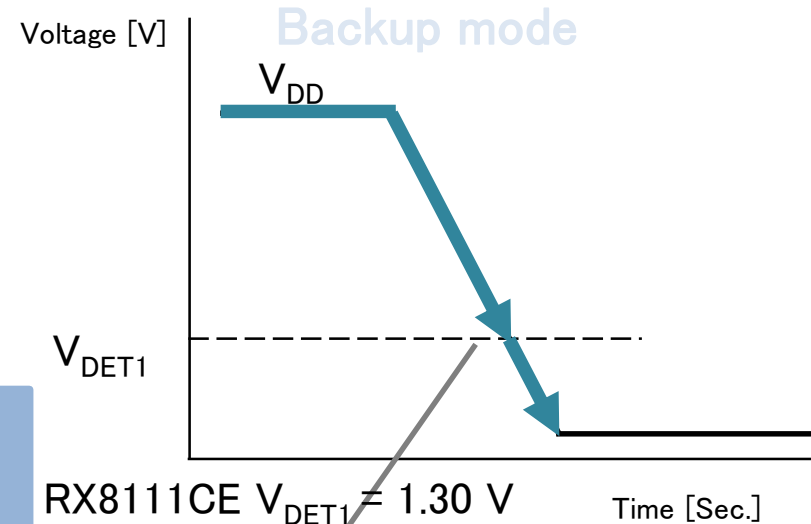
$V_{DD} > V_{DET1}$
Power is supplied from Main Power Supply
 Normal mode



RX8111CE battery backup switchover



When $V_{DD} \leq V_{DET1}$
Power supply changes from
Main power supply to Backup
battery



When $V_{DD} \leq V_{DET1}$, SW1 from ON to OFF
SW2 from OFF to ON
SW3 from OFF to ON



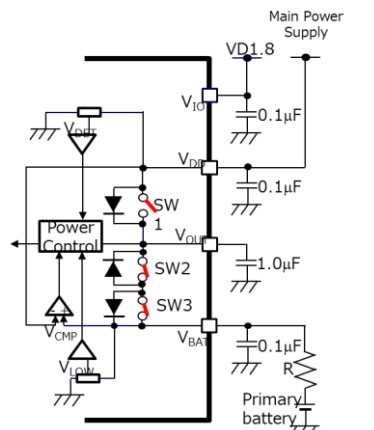
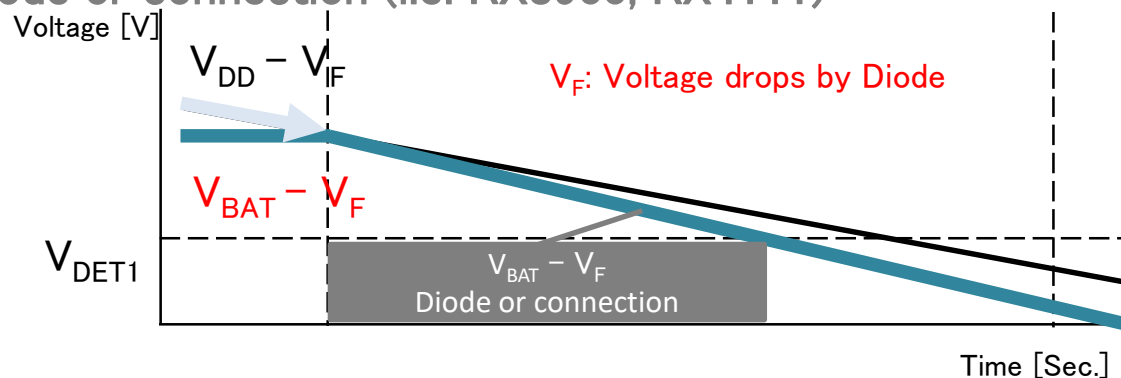
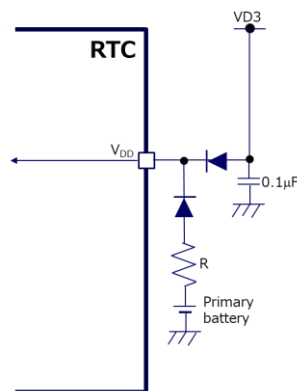
RX8111CE battery backup switchover

When Diode or connection: $V_{DD} - V_F \leq V_{BAT} - V_F$

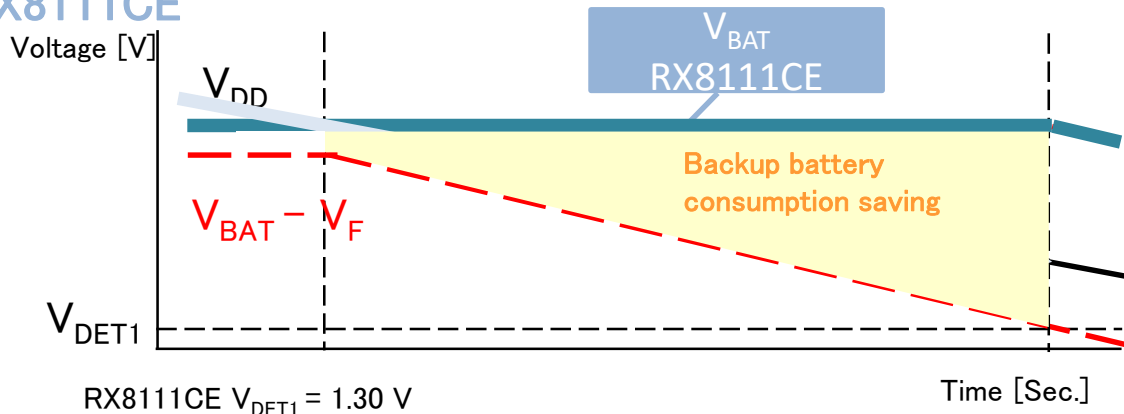
RX8111CE: $V_{DD} \leq V_{DET1}$

the power supply changes from V_{DD} to Backup battery

Diode or connection (i.e. RX8900, RX4111)



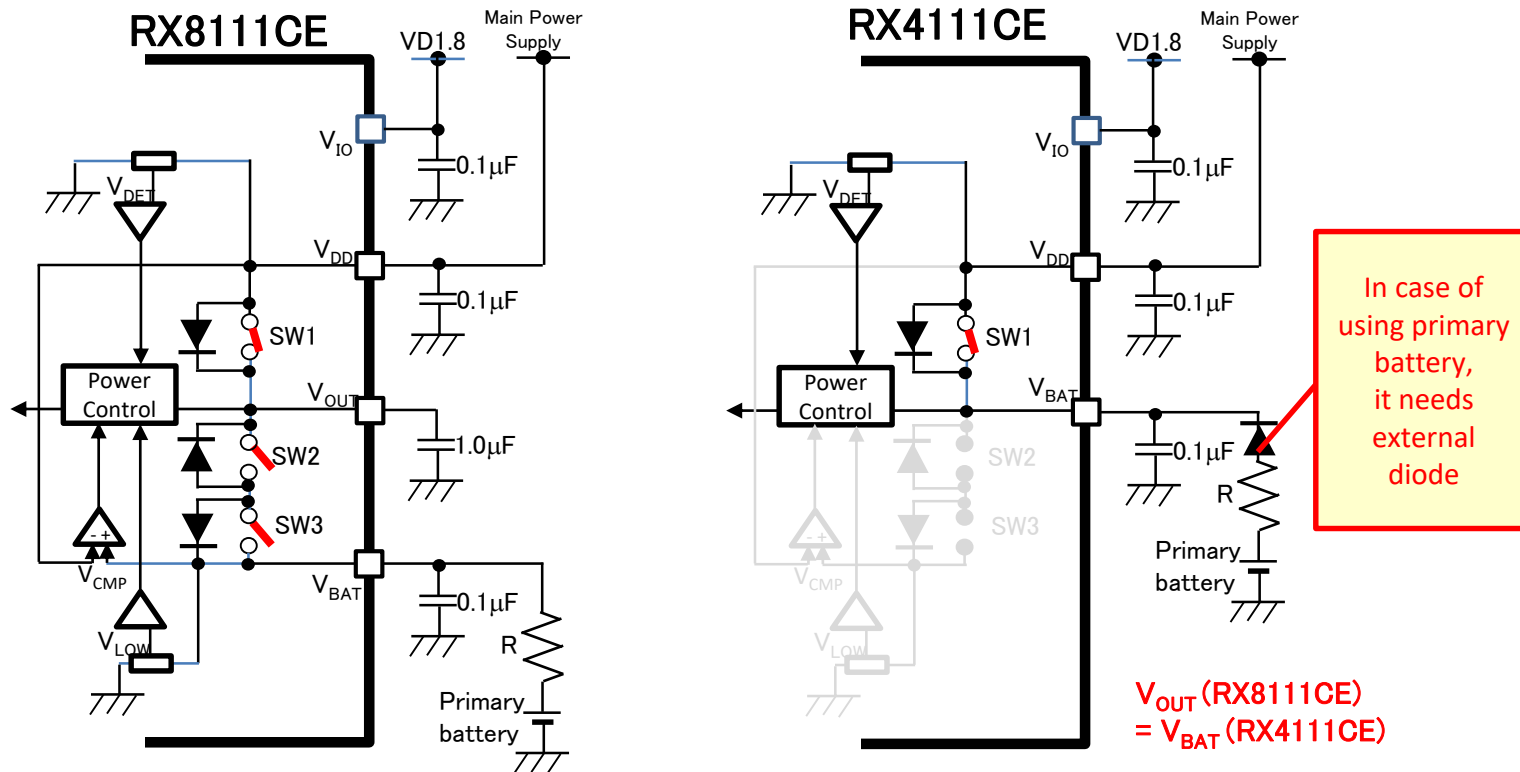
RX8111CE



RX8111CE $V_{DET1} = 1.30\text{ V}$



Battery backup switchover function comparison

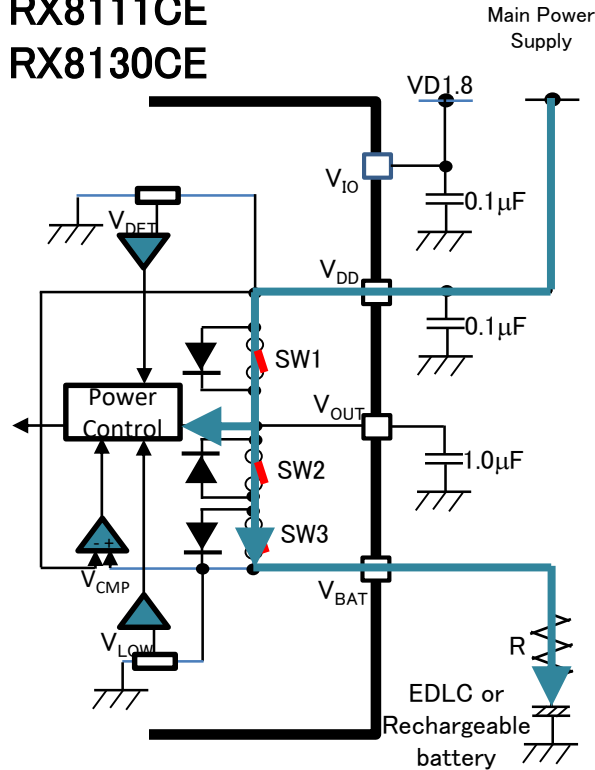


The interface of RX4111CE is SPI, so there are less pins compare to RX8111CE which is I2C. There is **no** V_{OUT} pin and differences are shown in the figure. Please note for RX4111, that the backup battery will be consumed under the condition: $V_{DET1} < V_{DD} < V_{BAT}$



Battery backup switchover function comparison

RX8111CE
RX8130CE



Internal circuit of RX8111CE and RX8130CE for battery backup switchover function are the same.

RX8130CE:

Offers 3 levels of charge stop and recharge voltage:

Charge stop voltage = 2.92, 3.02, 3.08 V Typ.

Recharge voltage = 2.87, 2.97, 3.03 V Typ.

*You can set it by register

RX8111CE:

It only stops at $V_{BAT} \geq V_{DD}$

Please see page 3

Charge stop voltage,

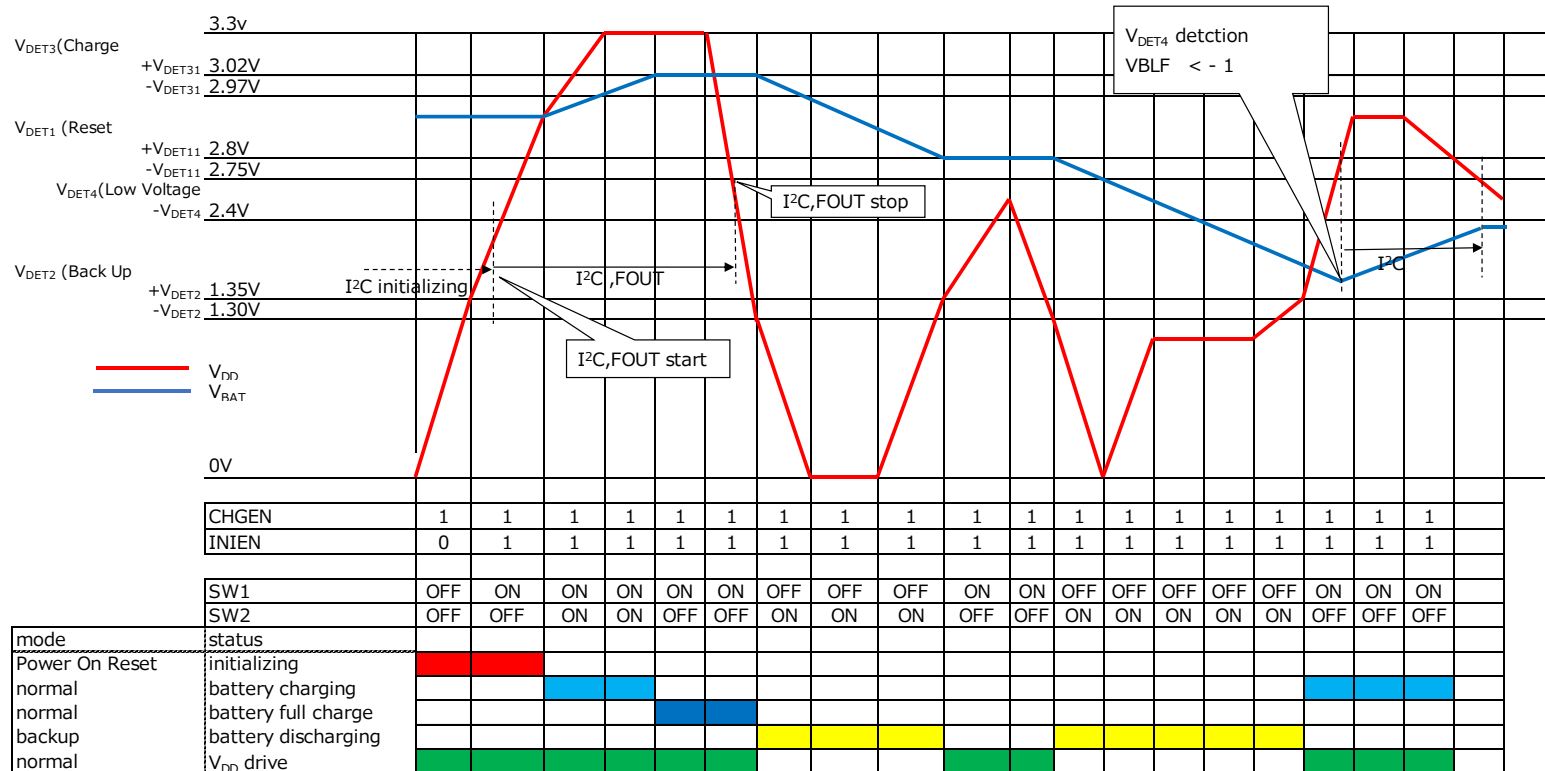
Recharge voltage,

$V_{DD} < V_{BAT}$ Charge stop



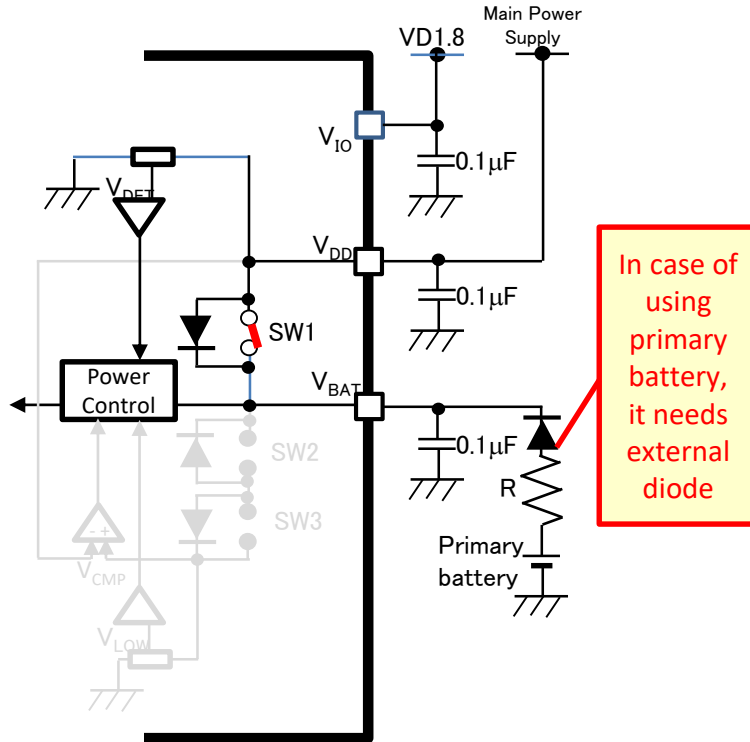
Li-Battery Charge Control – RX8130

RX8130CE can detect a full charge of secondary battery via a voltage detector on V_{BAT} . It furthermore switches the power supply to backup only if VDD dropped to min. voltage, which extends the available backup time and is especially suitable for battery-powered equipment.

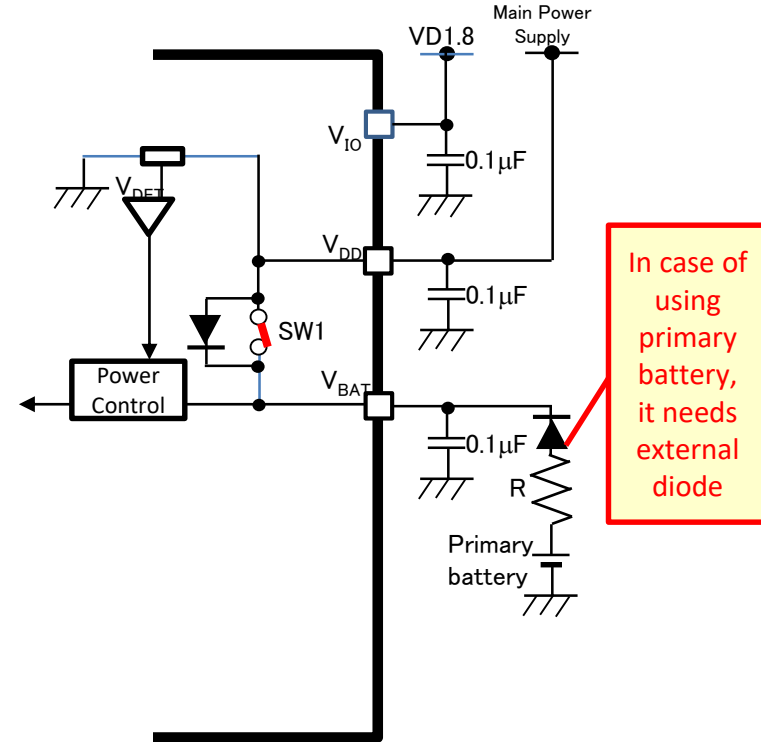


Battery backup switchover function comparison

RX4111CE



RX8900CE



Internal circuit of RX4111CE and RX8900CE for battery backup switchover function are the same.

RX8130CE, RX8111CE, RX4111CE operate V_{DD} detection all the time while in normal operation

($V_{DD} > V_{DET1}$)

V_{DET} of RX8900CE is intermittent detection.

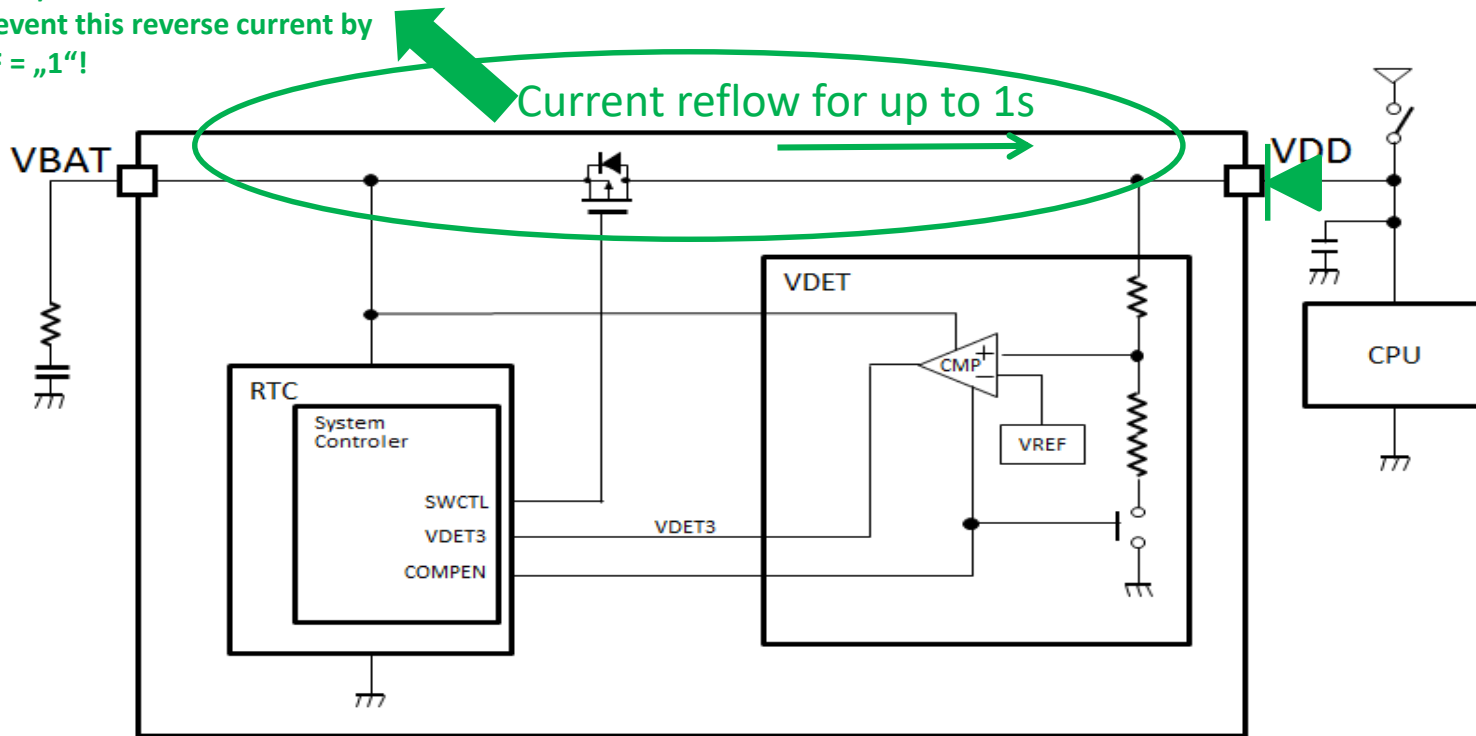


Epson Power-Switch Options for RTCs – RX8900/4111/6110

Current reflow for up to 1s till the Switch opens for the next VDET measurement!

→ Can be prevented with external diode right at VDD-pin (HF-filter C needs to be behind diode as it would buffer VDD for too long time!!)

RX6110 can prevent this reverse current by setting BKSOFF = „1“!



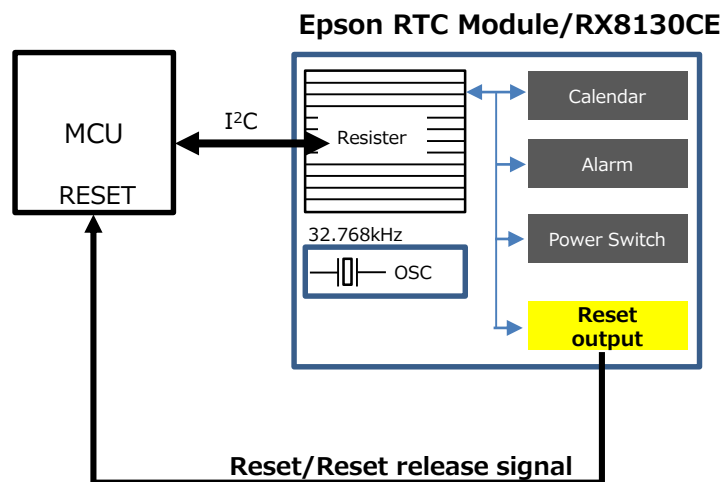
Optimized for use with a super-cap or capacitor as backup-power supply which needs to be charged from the main supply being a power-line.



Reset Output – RX8130CE



RX8130CE generates a Reset/Reset release signal depending on the VDD supply voltage. This Reset-control function prevents problems with toggling I/O ports of connected MCUs and thus eliminates the need for an external Reset IC, contributing to a reduction in the number of parts and cost.



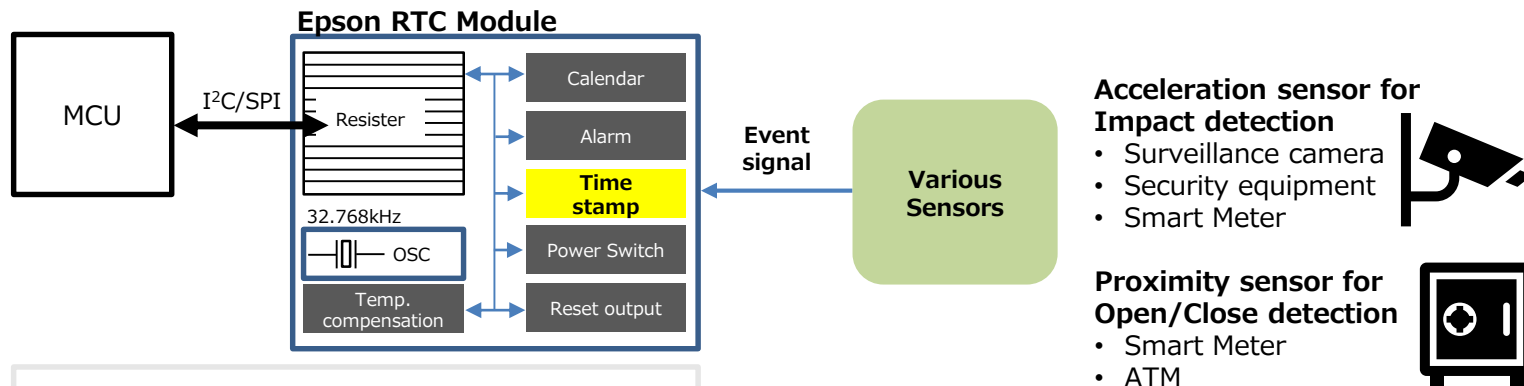
	Symbol	Detection voltage (typ.)	Setting
Reset	$+V_{DET11}$	2.75 V	RSVESEL "0" (default)
Reset Release	$-V_{DET11}$	2.80V	
Reset	$+V_{DET12}$ (X1B000311000100)	2.70 V	RSVESEL "1"
Reset Release	$-V_{DET12}$ (X1B000311000100)	2.75 V	
Reset	$+V_{DET12}$ (X1B000311000200)	1.60 V	RSVESEL "1"
Reset Release	$-V_{DET12}$ (X1B000311000200)	1.65 V	



Time Stamp / Even Recording – RX8111/RX8804

This function records the time data when an event (signal) is detected.

- RX8111CE and RX8804CE can receive event signals directly from the event input pin (EVIN), enabling RTC operation even when the MCU is in standby mode.
- RX8111CE and RX4111CE can record 8 times clock time data. (User can select first/last 8 even recording)



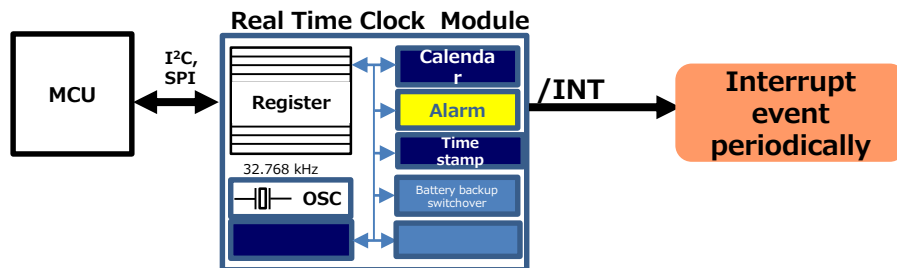
Event trigger options

- EVIN pin input (RX8111CE, RX8804CE)
- Interlock with RTC's internal operation
- Bus access



Wake-up Timer – RX8111

- Repeatedly outputs an interrupt signal at a specified fixed time interval.
- Can be used for regular activation and operation timing of CPU and peripheral devices.
- **Suitable for regular Wake up / Sleep solutions**



Timer source clock selectable from 4096 Hz, 64 Hz, 1 Hz, 1/60 Hz

Timer counter setting	Timer source clock			
	4096 Hz	64 Hz	1 Hz	1/60 Hz
1	244.14 μ s	15.625 ms	1 s	1 min
:	:	:	:	:
16777216	1.13 h	72.81 h	4660 h	31.9 year

Auto release after interrupt output from /INT pin when timer completes:

This operation is auto repeated with a selected cycle;

It can be used like a Watchdog timer



Ex. Maintenance notice

Filter cleaning

Oil change

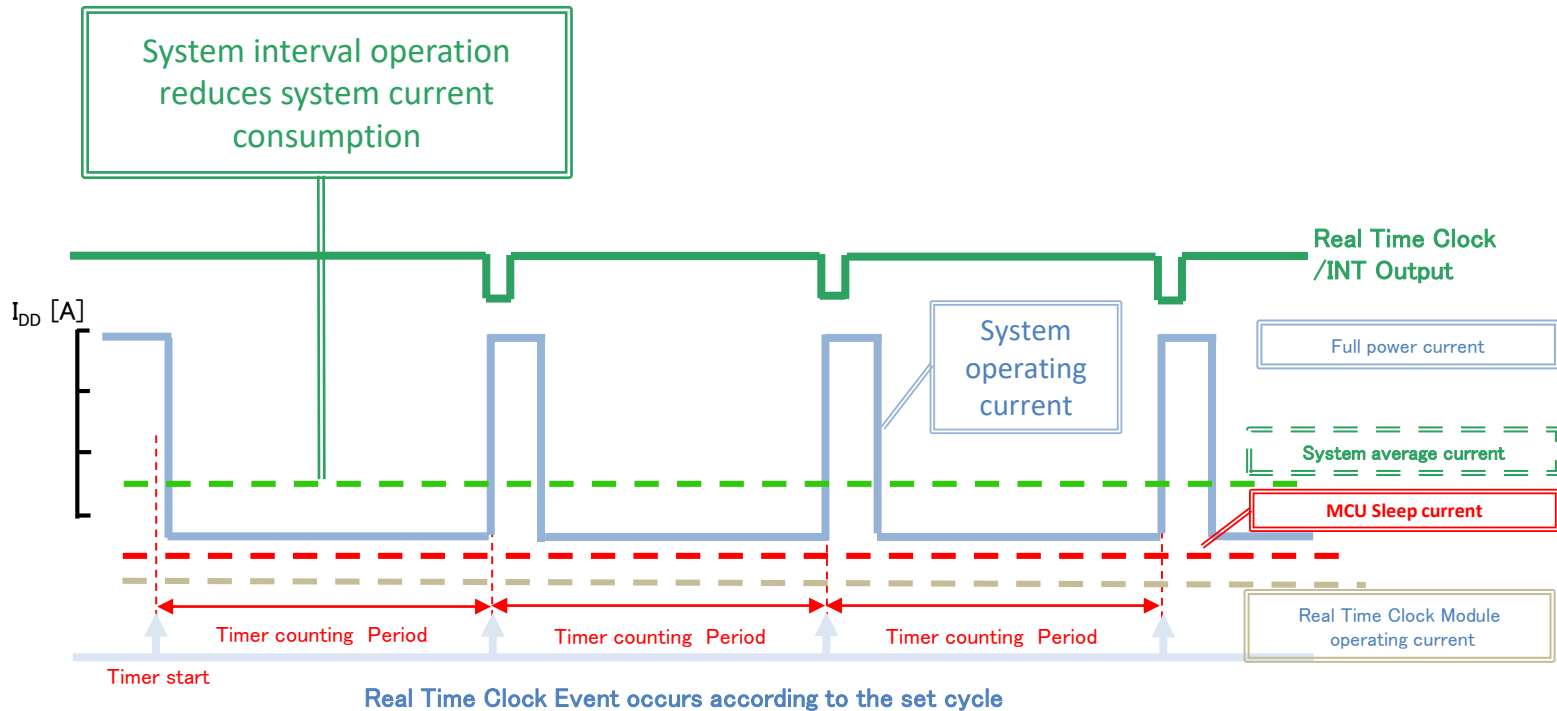


Ex. System monitoring

Measures at /hours

Wake-up Timer – Power Saving

The Real Time Clock Modules wake-up timer function enables MCU to operate in interval mode and thus reduces system power consumption.



EPSON RTC

Lineup




Rev1.4






















RTC Large Lineup

REAL TIME CLOCK MODULE









► SPI-Bus & I²C-Bus

Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
103	RX6110SA	 NEW 10.1×7.4×3.3	Low current consumption Power Switching	✓	✓	✓	✓	0.13	1.1 to 5.5

► SPI-Bus









Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
104	RX-4803SA	 10.1×7.4×3.3	Built-In DTCXO	✓	✓	-	✓	0.75	1.6 to 5.5
	RX-4803LC	 3.6×2.8×1.2							
105	RX-4035SA	 10.1×7.4×3.3	Built-In Timestamp and Power Switching	✓	✓	-	-	0.35	1.0 to 5.5
	RX-4035LC	 3.6×2.8×1.2						0.4	
106	RX-4045SA	 10.1×7.4×3.3	High-Stability	✓	✓	-	-	0.48	1.15 to 5.5
	RX-4045NB	 6.3×5.2×1.4							
107	RX-4581NB	 6.3×5.2×1.4	Built-In SRAM	✓	✓	✓	✓	0.4	1.6 to 5.5
108	RX-4571SA	 10.1×7.4×3.3	Low Backup Voltage	✓	✓	-	✓	0.32	1.0 to 5.5
	RX-4571NB	 6.3×5.2×1.4							
	RX-4571LC	 3.6×2.8×1.2							
109	RTC-4701JE	 7.3×6.2×1.5	Built-In Temperature Sensor	✓	✓	-	✓	0.5	1.6 to 5.5
	RTC-4701NB	 6.3×5.2×1.4							
110	RTC-4574SA	 10.1×7.4×3.3	Simple Function	✓	✓	-	✓	0.5	1.6 to 5.5
	RTC-4574JE	 7.3×6.2×1.5							
	RTC-4574NB	 6.3×5.2×1.4							
111	RX-4574LC	 3.6×2.8×1.2		✓	✓	-	✓	0.35	1.3 to 5.5
112	RTC-4543SA	 10.1×7.4×3.3		✓	-	-	-	1.0	1.4 to 5.5
	RTC-4543SB	 11.6×8.0×2.0							
113	RX-4575LC	 3.6×2.8×1.2	Built-In external event detection	✓	✓	-	✓	0.35	1.3 to 5.5

► I²C-Bus





Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
114	RX8010SJ	 NEW 7.0×6.0×2.65	Low current consumption	✓	✓	✓	✓	0.16	1.1 to 5.5
115	RX-8571SA	 10.1×7.4×3.3	Low power consumption 128 bit User RAM Long-running timer (5000 hours)	✓	✓	✓	✓	0.2	1.3 to 5.5
	RX-8571NB	 6.3×5.2×1.4							
	RX-8571LC	 3.6×2.8×1.2						0.22	
	RTC-8564JE	 7.3×6.2×1.5							
116	RTC-8564NB	 6.3×5.2×1.4	Low current consumption	✓	✓	-	✓	0.275	1.1 to 5.5
	RX-8564LC	 3.6×2.8×1.2							1.3 to 5.5
117	RX-8803SA	 10.1×7.4×3.3	Built-In DTCXO	✓	✓	-	✓	0.75	1.6 to 5.5
	RX-8803LC	3.6×2.8×1.2							

REAL TIME CLOCK MODULE







► I²C-Bus

Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
118	RX-8035SA	 10.1×7.4×3.3	Built-In Timestamp and Power Switching	✓	✓	-	-	0.35	1.0 to 5.5
	RX-8035LC	 3.6×2.8×1.2						0.4	
119	RX-8025SA	 10.1×7.4×3.3	High-Stability	✓	✓	-	-	0.48	1.15 to 5.5
	RX-8025NB	 6.3×5.2×1.4							
120	RX-8731LC	 3.6×2.8×1.2	ID-ROM + EEPROM	✓	✓	✓	✓	0.35	1.3 to 5.5
121	RX-8581SA	 10.1×7.4×3.3	Simple Function	✓	✓	-	✓	0.45	1.6 to 5.5
	RX-8581JE	 7.3×6.2×1.5							
	RX-8581NB	 6.3×5.2×1.4							

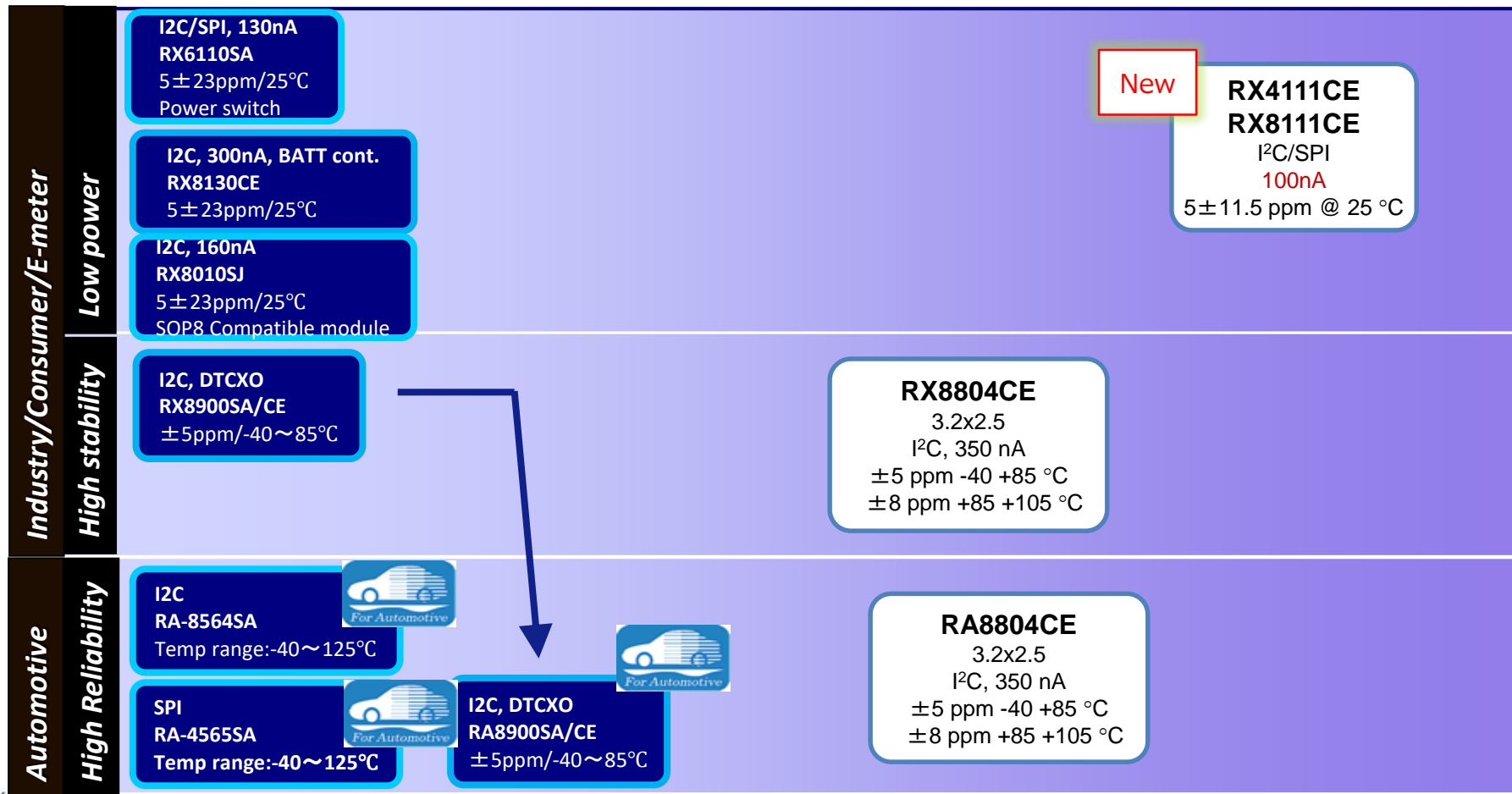
► Parallel Interface

Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
122	RTC-7301SF	 10.2×7.8×2.0	Built-In Temperature Sensor	✓	✓	-	✓	0.6	1.6 to 5.5
	RTC-7301DG	 DIP 18 pin	Available Alarm and Timer	✓	✓	-	✓	0.6	1.6 to 5.5
123	RTC-72421	 DIP 18 pin	4-bit Simple Function	✓	✓	-	✓	0.9	2.0 to 5.5
	RTC-72423	 16.3×12.2×2.8		✓	✓	-	✓	0.9	2.0 to 5.5

► For Automotive SPI-Bus, I²C-Bus

Page	Model	External dimensions (mm) (t: Max.)	Features	FOUT	Alarm	Memory	Timer	Back up current [μA]	Voltage range [V]
124	RA4803SA	 NEW 10.1×7.4×3.3	AEC-Q200 SPI-Bus Built-In DTCXO	✓	✓	-	✓	0.75	1.6 to 5.5
125	RA8803SA	 NEW 10.1×7.4×3.3	AEC-Q200 I ² C-Bus Built-In DTCXO	✓	✓	-	✓	0.75	1.6 to 5.5
126	RA-4565SA	 10.1×7.4×3.3	AEC-Q200 SPI-Bus Extended operating temperature range (-125°C)	✓	✓	-	✓	0.5	1.5 to 5.5
127	RA-4574SA	 10.1×7.4×3.3	AEC-Q200 SPI-Bus	✓	✓	-	✓	0.5	1.6 to 5.5
128	RA-8565SA	 10.1×7.4×3.3	AEC-Q200 I ² C-Bus Extended operating temperature range (-125°C)	✓	✓	-	✓	0.55	1.7 to 5.5
129	RA-8581SA	 10.1×7.4×3.3	AEC-Q200 I ² C-Bus	✓	✓	-	✓	0.45	1.6 to 5.5

RTC Promotion Products



RTC New Products Summary

	RX8130CE	RX8900CE/SA	RX8804CE	RX81111CE	RX41111CE
Availability	MP	MP	MP	MP	MP
Size	✓✓✓ 3.2x2.5x1.0 (CE)	✓✓✓ 10.1x7.4x3.3 (SA) 3.2x2.5x1.0 (CE)	✓✓✓ 3.2x2.5x1.0 (CE)	✓✓✓ 3.2x2.5x1.0 (CE)	✓✓✓ 3.2x2.5x1.0 (CE)
Interface	I2C	I2C	I2C	I2C	SPI
Low Power	✓✓ 300nA	✓ 700nA	✓✓ 350nA	✓✓✓ 100nA	✓✓✓ 100nA
High Stability	✓ 5±23ppm / +25C	✓✓✓ UA: ±3.4ppm/-40~85C UB: ±5ppm/-40~85C	✓✓✓ UA: ±3.4ppm/-40~85C UB: ±5ppm/-40~85C	✓✓ 5±11.5ppm /+25C	✓✓ 5±11.5ppm /+25C
Power Switching	✓	✓	-	✓	✓
Time Stamp	-	-	✓ 1 TS	✓8 TS	✓8 TS
EVIN Pin	-	-	✓	✓	-
Reset Output	✓	-	-	-	-

•UA : ± 3.4 ppm / -40°C~+85°C
± 8.0 ppm / -40°C~+105°C

•UB : ± 5.0 ppm / -40°C~+85°C
± 8.0 ppm / -40°C~+105°C



RTC Easy Selection Guide

		RX6110SA	RX8010SJ	RX8130CE	RX-8035SA/LC RX-4035SA/LC	RX8900CE	RX-8803SA/LC RX-4803SA/LC	RX8804CE RA8804CE	RX8111CE RX4111CE
Size		10.1×7.4×3.3mm (SA)	7.0×6.0×2.4mm (SJ)	3.2x2.5x1.0mm(CE)	10.1×7.4×3.3mm (SA) 3.6x2.8x1.2mm(LC)	3.2x2.5x1.0mm(CE)	10.1×7.4×3.3mm (SA) 3.6x2.8x1.2mm(LC)	3.2x2.5x1.0mm(CE)	3.2x2.5x1.0mm(CE)
Crystal		Built-in	Built-in	Built-in	Built-in	Built-in	Built-in	Built-in	Built-in
Interface		I2C/SPI	I2C	I2C	I2C/SPI	I2C	I2C/SPI	I2C	I2C
Frequency tolerance		5±23ppm / +25°C	5±23ppm / +25°C	5±23ppm / +25°C	5±5ppm./+25°C 5±23ppm / +25°C	UA:±3.4ppm/-40~85°C UB:±5ppm/-40~85°C	UA:±3.4ppm/-40~85°C UB:±5ppm/-40~85°C	±1.9ppm/0~50°C ±3.4ppm/-40~85°C ±8ppm/-40~105°C	5±11.5ppm / +25°C
Power voltage		1.6~5.5V	1.6~5.5V	1.6~5.5V	2.4~5.5V	1.6~5.5V	1.6~5.5V	1.6~5.5V	1.6~5.5V
Clock voltage		1.1~5.5V	1.1~5.5V	1.1~5.5V	1.0~5.5V	1.6~5.5V	1.6~5.5V	1.5~5.5V	1.1~5.5V
Current consumption	Typ.	130nA / 3V	160nA / 3V	300nA / 3V	350nA / 3V	700nA / 3V	750nA / 3V	350nA / 3V	100nA
	Max.	250nA / 3V	320nA / 3V	500nA / 3V	1200nA / 3V	1400nA / 3V	2100nA / 3V	1500nA	450nA
Clock, calendar		■	■	■	■	■	■	■	■
Alarm		■	■	■	■	■	■	■	■
Timer		■	■	■	■	■	■	■	■
Frequency output		■	■	■	■	■ Temp. Compensated	■ Temp. Compensated	■ Temp. Compensated	■
Digital offset function		■	-	■	■	-	-	-	-
Event Detection		-	-	-	2 EVIN	-	-	1 EVIN	1 EVIN
Reset-Controller		-	-	■	■	-	-	-	-
DTCXO		-	-	-	-	■	■	■	-
Battery power switching		■	-	■	■	■	-	-	■
User RAM		SRAM 128bit	SRAM 128bit	SRAM 32bit	-	-	-		512bit (dependent on used functions)
Remarks		-	-	Charge function for lithium secondary battery. Reset function with delay.	Event detection and Timestamp function	Temp sensor output function	1/100s time register.	Wide operating temp. range Event detection and Timestamp function High accuracy time reading function	Ultra low power with power switch function. Event detection and Timestamping function

RTC Promotion Products – Spec. Comparision

Interface	Product name	Status	Specifications & conditions									Functions					
			Size [mm]	Operating temperature Ta [°C]		Frequency tolerance [x 10 ⁻⁶]				Backup current consumption [μA]		Time stamp	Power switch	Event pin	Memory	Timer	Others
				Min.	Max.	+25 °C	-40 to +85 °C	-40 to +105 °C	-40 to +125 °C	Typ. (3.0 V)	Max. (Ta)						
SPI 4 wire & I ² C	RX6110SA	MP	10.1 x 7.4	-40	+85	5±23	-	-	-	0.13	0.25	-	✓	-	SRAM 128 bit	16 bit x 1 ch. to 7.5 years	-
I ² C	RX8111CE	sampling MP Q2 2020	3.2 x 2.5	-40	+85	±11.5 ±23	-	-	-	0.1	0.45	8	✓	1	SRAM 512 bit	24 bit x 1 ch. to 32 years	-
	RX8804CE	MP		-40	+105	-	±3.4 ±5.0	±8.0	-	0.35	1.5	1	-	1	-	16 bit x 1 ch. to 7.5 years	SOUT
	RX8130CE	MP		-40	+85	5±23	-	-	-	0.3	0.5	-	✓	-	-	16 bit x 1 ch. to 7.5 year	Li-Battery charge control, Reset with a delay
	RX8900CE	MP		-40	+85	-	±3.4 ±5.0	-	-	0.7	1.4	-	✓	-	-	12 bit x 1 ch. to 2.8 days	Temp. sensor
SPI 4 wire	RX4111CE	sampling MP Q2 2020	3.2 x 2.5	-40	+85	±11.5 ±23	-	-	-	0.1	0.45	8	✓	-	SRAM 512 bit	24 bit x 1 ch. to 32 years	-



For Automotive

I ² C	RA8804CE (AEC-Q100)	MP	3.2 x 2.5	-40	+105	-	±3.4 ±5.0	±8.0	-	0.35	1.5	1	-	1	-	16 bit x 1 ch. to 7.5 years	SOUT
	RA8900CE (AEC-Q200)	MP		-40	+85	-	±3.4 ±5.0	-	-	0.7	1.4	-	✓	-	-	12 bit x 1 ch. to 2.8 days	Temp. sensor
SPI 4 wire	RA4803SA (AEC-Q200)	MP	10.1 x 7.4	-40	+85	-	±3.4 ±5.0	-	-	0.75	2.1	-	-	1	-	12 bit x 1 ch. to 2.8 days	-
	RA-4565SA (AEC-Q200)	MP		-40	+125	5±23	-	-	-	0.5	1.0	-	-	-	-	8 bit x 1 ch. to 4.25 hours	-



kHz TCXO & SPXO Road Map

32 kHz DTCXO

TG-3530SA

10.1x5.0
 $\pm 5 \text{ ppm } -40 \text{ } ^\circ\text{C}$ $+85 \text{ } ^\circ\text{C}$

TG-3541CE

3.2x2.5
 $\pm 5 \text{ ppm } -40 \text{ } ^\circ\text{C}$ $+85 \text{ } ^\circ\text{C}$
 $\pm 8 \text{ ppm } +85 \text{ } ^\circ\text{C}$ $+105 \text{ } ^\circ\text{C}$

TG-3541CEA

3.2x2.5
 $\pm 5 \text{ ppm } -40 \text{ } ^\circ\text{C}$ $+85 \text{ } ^\circ\text{C}$
 $\pm 8 \text{ ppm } +85 \text{ } ^\circ\text{C}$ $+105 \text{ } ^\circ\text{C}$



32 kHz SPXO

SG-3030CM

3.2x1.5
 $5 \pm 23 \text{ ppm @ } 25 \text{ } ^\circ\text{C}$
 $-40 \text{ } ^\circ\text{C}$ $+85 \text{ } ^\circ\text{C}$

SG-3031CM

3.2x1.5
 $5 \pm 23 \text{ ppm @ } 25 \text{ } ^\circ\text{C}$
 $-40 \text{ } ^\circ\text{C}$ $+105 \text{ } ^\circ\text{C}$

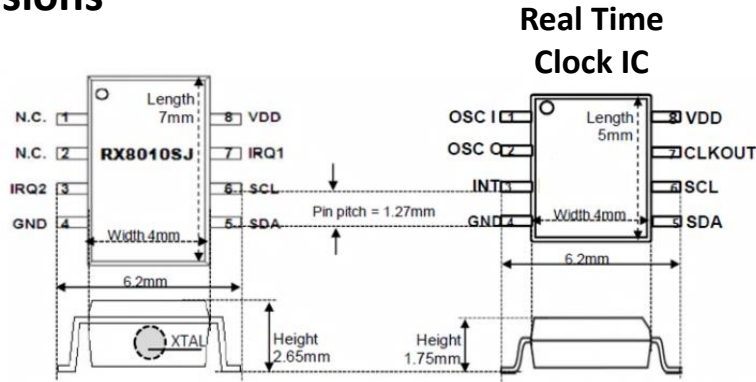
SG-3031CMA

3.2x1.5
 $5 \pm 23 \text{ ppm @ } 25 \text{ } ^\circ\text{C}$
 $-40 \text{ } ^\circ\text{C}$ $+105 \text{ } ^\circ\text{C}$



SOP 8 packaged RX8010SJ

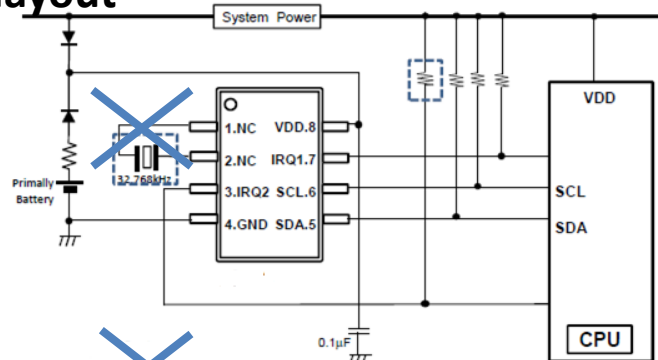
Dimensions



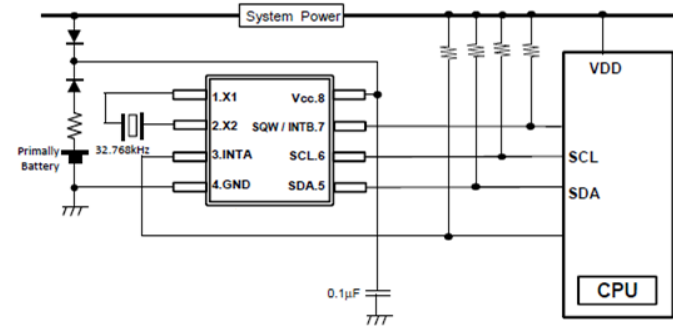
Replace RTC Ics like
Maxim DS1337S8+2
NXP PCF8563T/4F,118
Pericom PT7C4337A


Simple layout
Pre-adjusted for clock accuracy
Pre-optimized design of oscillation
High reliability

Circuit layout



Real Time Clock IC + 32kHz crystal



 Parts(32KHz) are unnecessary



RX-x803SA / LC Overview

Real time clock module with DTCXO

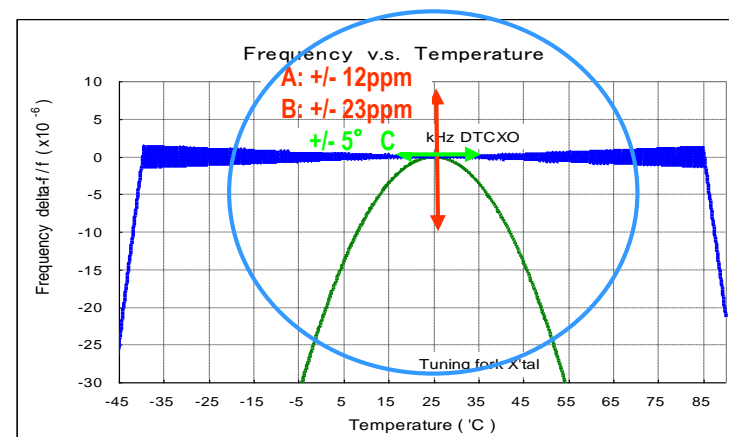
RX-x803SA / LC

Feature

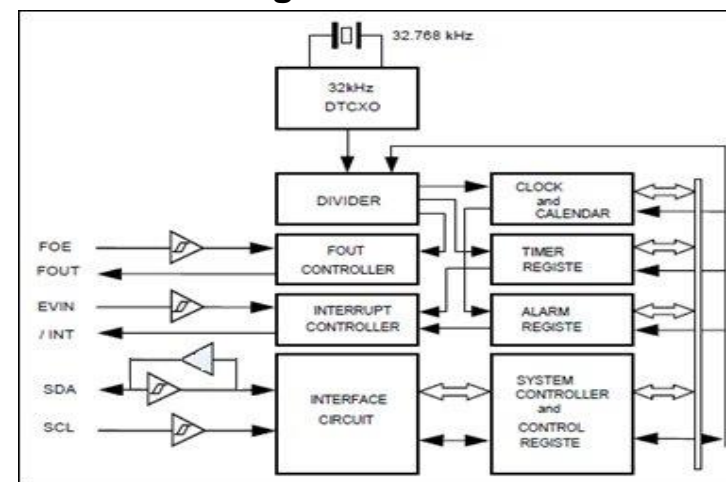
- ✓ Ultra High Stability
- ✓ Low current consumption : Typ. 0.8μA / 3V

Overview

		RX- 4803	RX- 8803
Interface type		4-wire serial	I ² C-bus
Stability	UA	$\pm 3.4 \times 10^{-6} / -40 \text{ to } +85^{\circ}\text{C} \times 1$	
	UB	$\pm 5.0 \times 10^{-6} / -40 \text{ to } +85^{\circ}\text{C} \times 2$	
	UC	$\pm 5.0 \times 10^{-6} / -30 \text{ to } +70^{\circ}\text{C} \times 2$	
	AA	$\pm 5.0 \times 10^{-6} / +25^{\circ}\text{C} \times 2$	
Voltage range		1.6 ~ 5.5 V (Back up) 2.2 ~ 5.5 V (Temp. compensated)	
Current consumption		0.8 μA Typ. 2.1 μA Max. (3.0V)	
Package type		SA : 10.1 x 7.4mm t=3.3mm Max. LC : 3.6 x 2.8mm t=1.2mm Max.	



Block diagram



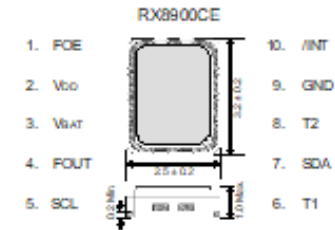
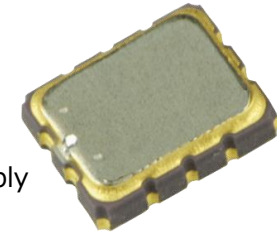
SA-PKG



LC-PKG

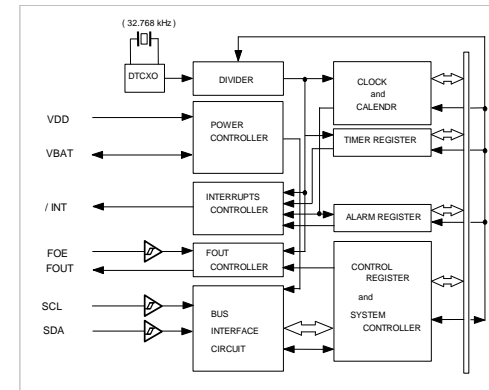
Built-in 32.768 kHz DTCXO, High Stability, Power switching

- Built-in frequency adjusted 32.768 kHz crystal unit and **DTCXO**
- Interface Type : I²C-Bus
- Selectable clock output : 32.768 kHz, 1024 Hz, 1 Hz
- **Auto power switching function** : Automatically switches to backup power supply by monitoring the VDD voltage
- Interrupt output : Wake up every minute or every second
- Alarm interruption : Day, date, hour, minute
- Auto repeat wakeup timer interruption (12 bit x 1ch.)
- Automotive grade available (RA8900CE)



Item		Symbol	Specs	
Operating Conditions	Operating supply voltage	V _{DD}	2.5 V to 5.5 V	
	V _{DD} detect voltage	V _{DET3}	2.3 V to 2.5 V	
	Operating temperature	T _a	-40 ° C to +85 ° C	
Characteristics	Stability	$\Delta f/f$	UA	$\pm 3.4 \times 10^{-6}$ (-40 ° C to 85 ° C) *equiv. to ± 9 s of mo. deviation
			UB	$\pm 5 \times 10^{-6}$ (-40 ° C to 85 ° C) *equiv. to ± 13 s of mo. deviation
	Current consumption	I _{DD2}	700 nA / Typ. 3 V 1,400 nA / Max. 3 V (Temp. Compensation interval: 2.0 s)	

■ Block diagram

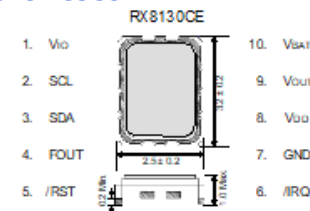
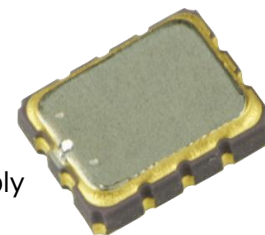


RX8130CE



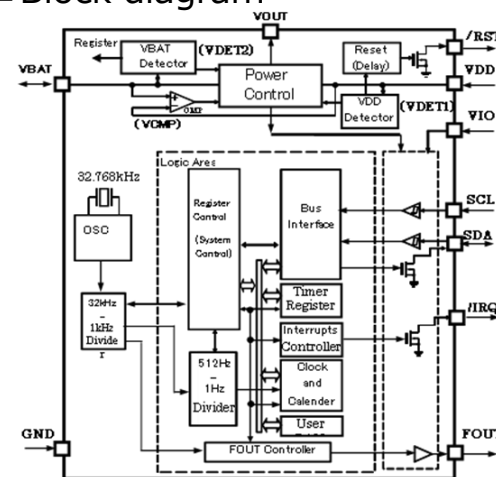
Built-in backup battery charge control function

- Built in frequency adjusted 32.768 kHz crystal unit
- Interface Type : I²C-Bus
- Low backup current : 300 nA Typ. / 3 V
- Auto power switching function : Automatically switches to backup power supply by monitoring the V_{DD} voltage
- **Backup battery charge control function : For the rechargeable battery**
- **Reset functions with a delay : Detect a main power supply and remove the reset**
- Interrupt output : Wake up every minute or every second
- Alarm interruption : Day, date, hour, minute, second
- Auto repeat wakeup timer interruption (16 bit x 1 ch.)
- Self-monitoring interruption : Crystal oscillation stop, V_{BAT} low, V_{DD} low



Item		Symbol	Specs
Operating Conditions	Operating supply voltage	V _{DD}	1.25 V to 5.5 V
	Operating temperature	T _a	-40 ° C to +85 ° C
	V _{DD} detect voltage	-V _{DET2}	1.2 V to 1.4 V (V _{DD} , Fall)
Characteristics	Frequency tolerance	Δf/f	B: +5 ± 23 x 10 ⁻⁶ / +25 ° C
	Oscillation start-up time	t _{STA}	1 s Max. (V _{DD} = 2.75 V to 5.5 V)
	Current consumption	I _{BAT}	300 nA / Typ. 3 V 500 nA / Max. 3 V (T _a = -40 ° C to +85 ° C)

■ Block diagram



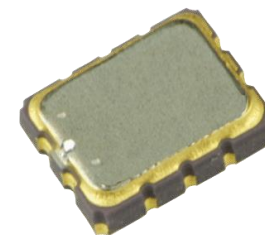
RX8804CE



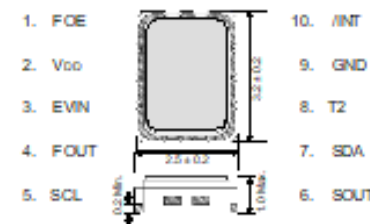
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Built-in 32.768 kHz DTCXO, High Stability, up to +105 ° C

- Built-in frequency adjusted 32.768 kHz crystal unit and **DTCXO**
- Interface Type : I²C-Bus
- Selectable clock output : 32.768 kHz, 1024 Hz, 1 Hz
- Time stamp function : **1 time stamped** from year to second
- Interrupt output : Wake up every minute or every second
- Alarm interruption : Day, date, hour, minute
- Auto repeat wakeup timer interruption (24 bit x 1 ch.)
- Self-monitoring interruption : Crystal oscillation stop, V_{BAT} low, V_{DD} low
- SOUT pin outputs that selected flag bit value (H or L)
- Automotive grade available (RA8804CE)

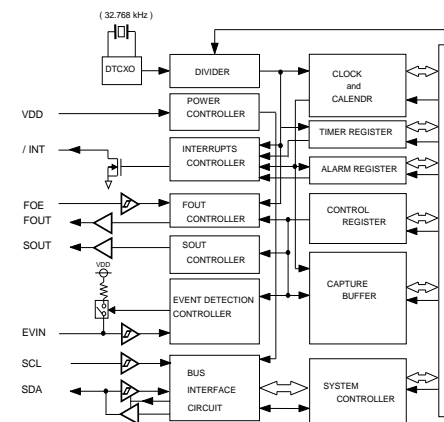


RX8804CE



Item		Symbol	Specs	
Operating Conditions	Operating supply voltage	V _{DD}	1.6 V to 5.5 V	
	Operating temperature	T _a	-40 ° C to +105 ° C	
Characteristics	Stability	Δf/f	XA	$\pm 3.4 \times 10^{-6}$ (-40 ° C to 85 ° C) *equiv. to ±9 s of mo. deviation $\pm 8 \times 10^{-6}$ (-40 ° C to 105 ° C)
			XB	$\pm 5 \times 10^{-6}$ (-40 ° C to 85 ° C) *equiv. to ±13 s of mo. deviation $\pm 8 \times 10^{-6}$ (-40 ° C to 105 ° C)
	Current consumption	I _{DD2}	350 nA / Typ. 3 V 1,500 nA / Max. 3 V (Temp. Compensation interval: 2.0 s)	

■ Block diagram

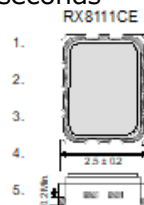
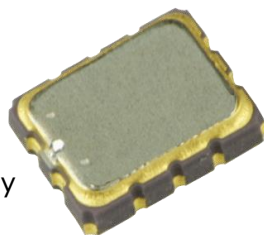


RX8111CE



Time stamp function and Low current consumption

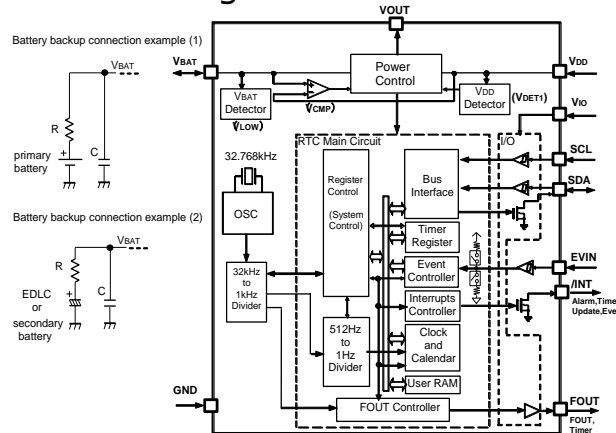
- Built in frequency adjusted 32.768 kHz crystal unit
- Interface Type : I²C-Bus
- Low backup current : **100 nA Typ.** / 3 V
- Auto power switching function : Automatically switches to backup power supply by monitoring the V_{DD} voltage
- Time stamp function : **8 times stamped** from year to 1/256 seconds
- Interrupt output : Wake up every minute or every second
- Alarm interruption : Day, date, hour, minute, second
- Auto repeat wakeup timer interruption (24 bit x 1 ch.)
- Self-monitoring interruption : Crystal oscillation stop, V_{BAT} low, V_{DD} low



Pin	Connection
1	VDD
2	VOUT
3	VBAT
4	FOUT
5	SCL
6	EVIN
7	SDA
8	VIO
9	GND
10	/INT

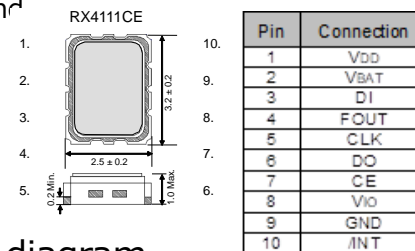
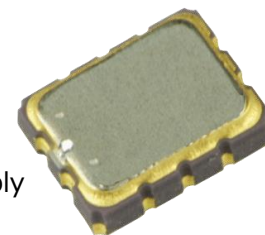
Item		Symbol	Specs	
Operating Conditions	Operating supply voltage	V _{DD}	1.6 V to 5.5 V	
	Operating temperature	T _a	-40 ° C to +85 ° C	
	V _{DD} detect voltage	-V _{DET1}	1.2 V to 1.6 V (V _{DD} , Fall)	
Characteristics	Frequency tolerance	Δf/f	A	±11.5 x 10 ⁻⁶ (+25 ° C)
			B	±23 x 10 ⁻⁶ (+25 ° C)
	Oscillation start-up time	t _{STA}	0.3 s Typ. / 1 s Max. (V _{DD} = 2.75 V to 5.5 V)	
	Current consumption	I _{BAT}	100 nA / Typ. 3 V 450 nA / Max. 3 V (T _a = -40 ° C to +85 ° C)	

■ Block diagram



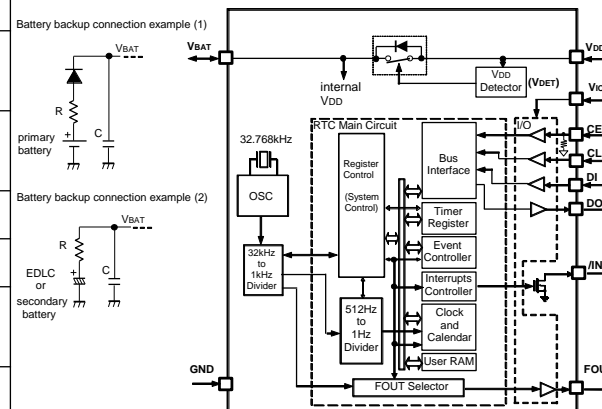
SPI, Time stamp function and Low current consumption

- Built in frequency adjusted 32.768 kHz crystal unit
- Interface Type : SPI-Bus (4 wire, 1 MHz)
- Low backup current : **100 nA Typ.** / 3 V
- Auto power switching function : Automatically switches to backup power supply by monitoring the V_{DD} voltage
- Time stamp function : **8 times stamped** from year to 1/256 seconds
- Interrupt output : Wake up every minute or every second
- Alarm interruption : Day, date, hour, minute, second
- Auto repeat wakeup timer interruption (24 bit x 1 ch.)
- Self-monitoring interruption : Crystal oscillation stop, V_{BAT} low, V_{DD} low



Item	Symbol	Specs
Operating Conditions	Operating supply voltage	V_{DD} 1.6 V to 5.5 V
	Operating temperature	T_a -40 ° C to +85 ° C
	V_{DD} detect voltage	$-V_{DET1}$ 1.2 V to 1.6 V (V_{DD} , Fall)
Characteristics	Frequency tolerance	<div>A</div> <div>B</div> $\Delta f/f$ $\pm 11.5 \times 10^{-6}$ (+25 ° C) $\pm 23 \times 10^{-6}$ (+25 ° C)
	Oscillation start-up time	t_{STA} 0.3 s Typ. / 1 s Max. ($V_{DD} = 2.75$ V to 5.5 V)
	Current consumption	I_{BAT} 100 nA / Typ. 3 V 450 nA / Max. 3 V ($T_a = -40$ ° C to +85 ° C)

■ Block diagram



RTC Drivers, Documentation and Support Tools

<https://www5.epsondevice.com/en/>

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Real Time Clock

Epson's wide range of Real Time Clock Modules (RTC) with built-in XTAL save power, provide superior accuracy, and simplify system design. Thanks to a rich set of optional functions, such as alarms and time stamps, RTCs can cover multiple additional tasks beside the time keeping.

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Recommended Products

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Model	Size [mm]	Feature	Voltage Range [V]	Frequency tolerance [x10 ⁻⁶]	Back up Current [μA]	Power Switching	Time stamp	Memory	RoHS REACH	Brief Sheet Application manual	Linux Driver	Inventory
RX8111CE	3.2 x 2.5 x 1.0	I ² C-Bus, Low Power, 8 time stamps	1.1 to 5.5	A : ±11.5 / +25°C B : ±23.0 / +25°C	0.1	✓	✓	✓	RoHS REACH	BriefSheet AppManual (ETM61E-01)	↓	RX8111CE
RX4111CE	3.2 x 2.5 x 1.0	SPI-Bus, Low Power, 8 time stamps	1.1 to 5.5	A : ±11.5 / +25°C B : ±23.0 / +25°C	0.1	✓	✓	✓	RoHS REACH	BriefSheet		RX4111CE
RX8804CE	3.2 x 2.5 x 1.0	I ² C-Bus Built-in DTCXO, High Stability	1.5 to 5.5	XA : ±3.4 / -40 to +85°C ±8.0 / +85 to +105°C XB : ±5.0 / -40 to +85°C ±8.0 / +85 to +105°C	0.35		✓		RoHS REACH	BriefSheet AppManual (ETM59E-05)	↓	RX8804CE

Application Manuals

- Detailed Information
- Link to Application Manuals:

<http://www5.epsondevice.com/en/quartz/product/rtc>

RTC Drivers, Documentation and Support Tools

<https://www5.epsondevice.com/en/>

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Real Time Clock Module Information

Features / Use cases / Unique Functions

The convenient tools Excel, Documents, etc

Evaluation board (RX8900CE/RX8804CE) [G](#)

RX8111CE Battery backup switchover function [G](#)

RX8111CE Time stamp function [G](#)

RX8111CE Wake up timer function [G](#)

RX4111CE Battery backup switchover function [G](#)

RX8804CE, RA8804CE SOUT Function [G](#)

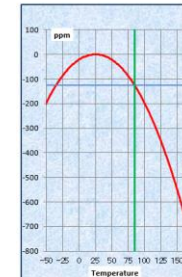
Overcoming Common Design Challenges: Suggestion with Real Time Clock Module(RTC) [G](#)

RX8900 / RX8804 Evaluation Tools

Linux® driver download

The convenient tools for Real Time Clock Modules

Contents	Overview	Products	Release	D/L
Calculation for Clock Stability vs Temperature	As for this Excel, a clock error by a clock precision error by a temperature characteristic of 32.768 kHz crystal and an error of oscillation frequency is calculated	Non DTCXO Real Time Clock Modules, and 32.768 kHz OSC(XO)	2020/09/18	D/L
Calculation for Battery Backup Time	This Excel calculates the battery backup time when coin battery and EDLC were used.	All Real Time Clock Modules products, and 32.768 kHz OSC(XO)	2020/09/18	D/L
Calculation for Data of Digital Offset Function	This Excel calculates correct logical data of compensation when "digital offset function" is used.	Real Time Clock Modules in built in Digital offset Function	2020/09/18	D/L



Enter values in the yellow cells only

Calculate the amount of frequency drift and clock error under different temperature conditions.

Temperature of crystal oscillator					
85	-50 to +150 degree			-126	ppm
0	Error /1 Hour	Error /day	Error /Month	Error /Year	
Hours	0	0	0	-1	
Minutes	0	0	-5	-6	
Seconds	-0.4	-10.8	-26.5	-13.5	

Enter values in the yellow cells only

Calculate the amount of clock drift after some amount of time has elapsed for a given amount of frequency drift (ppm).

Linux Drivers

- Simplify Design IN

- Link to Drivers:

http://www5.epsondevice.com/en/quartz/tech/linux_for_rtc/index.html





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